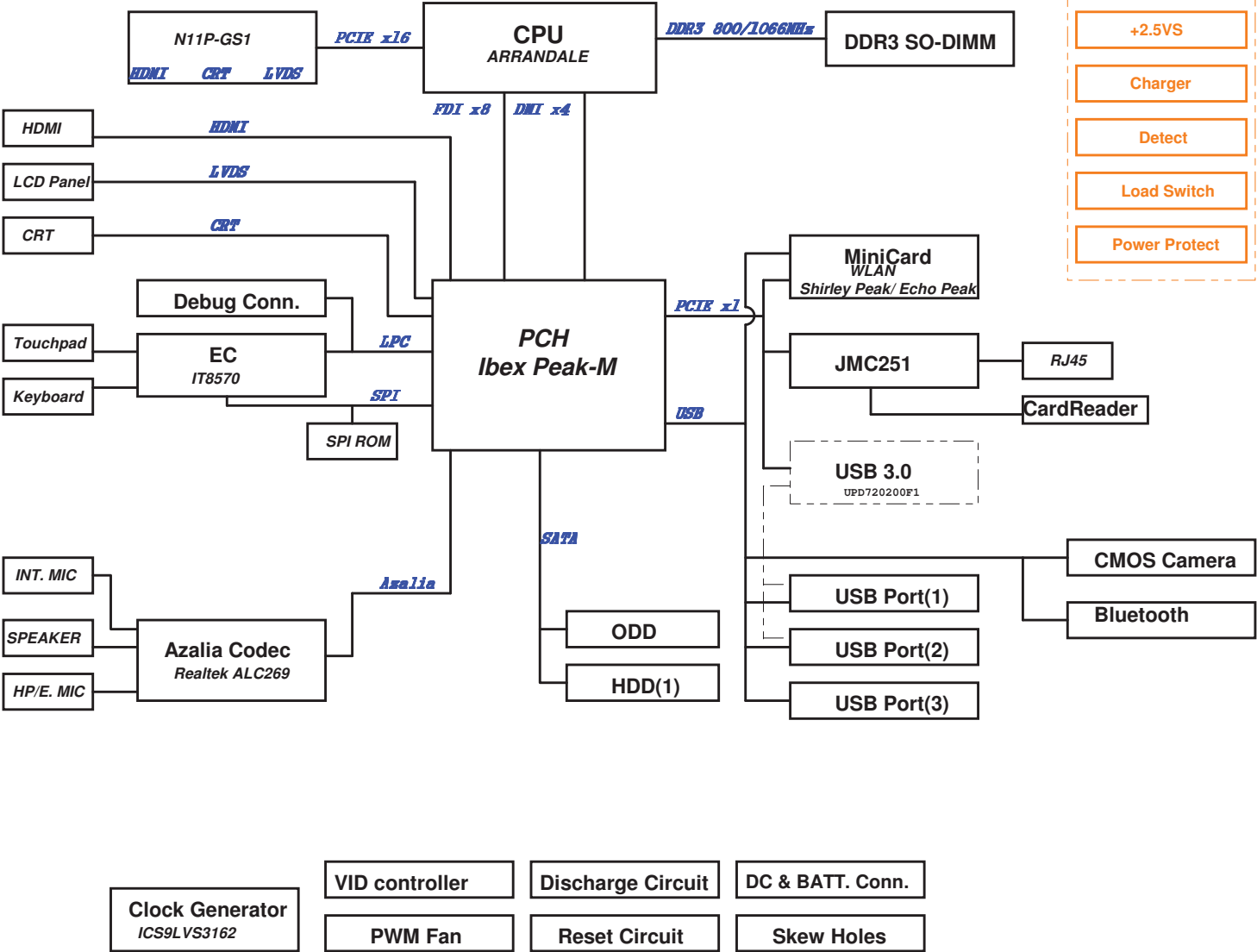


K42Jv SCHEMATIC Revision 2.0

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PCH IBEX
GPIO

PCH_IBEX GPIO	Use As	Signal Name	Internal & External Pull-up/down	Power
GPIO 00	GPO	-	-	+3VS
GPIO 01	GPO	-	INT TBD	+3VS
GPIO [2:5]	Native	-	EXT PU	+5VS
GPIO 06	GPO	-	INT TBD	+3VS
GPIO 07	GPI	USB30_SMIB	EXT PU	+3VS
GPIO 08	GPI	EC_SMI#	EXT PU & INT PU	+3VSUS
GPIO 09	Native	OC5#	EXT PU	+3VSUS
GPIO 10	Native	OC6#	EXT PU	+3VSUS
GPIO 11	GPI	EC_SCI#	EXT PU	+3VSUS
GPIO 12	Native	-	EXT PU	+3VSUS
GPIO 13	GPO	-	-	+3VSUS
GPIO 14	Native	OC7#	EXT PU	+3VSUS
GPIO 15	GPO	-	INT PD	+3VSUS
GPIO 16	GPO	DGPU_HOLD_RST#	EXT PU	+3VS
GPIO 17	GPI	DGPU_PWRGD_PCH	EXT PD	+3VS
GPIO 18	Native	CLK_REQ1#	EXT PU	+3VS
GPIO 19	GPO	-	-	+3VS
GPIO 20	Native	CLKREQ2_WLAN#_R	EXT PD	+3VS
GPIO 21	GPO	-	-	+3VS
GPIO 22	GPO	WLAN_BT_LED	EXT PD	+3VS
GPIO 23	Native	LPC_DRQ#1	-	+3VS
GPIO 24	GPO	-	-	+3VSUS
GPIO 25	Native	CLK_REQ3#	EXT PU	+3VSUS
GPIO 26	Native	CLK_REQ4#(USB 3.0)	EXT PU	+3VSUS
GPIO 27	Native	PCH_VRM_EN	INT WEAK PU	+3VSUS
GPIO 28	GPO	WLAN_ON	-	+3VSUS
GPIO 29	GPO	-	-	+3VSUS
GPIO 30	Native	ME_SusPwrDnAck	EXT PU	+3VSUS
GPIO 31	Native	ME_AC_PRESENT	EXT PU	+3VSUS
GPIO 32	Native	PM_CLKRUN#	EXT PU	+3VS
GPIO 33	GPI	PCH_SPI_OV_RW	INT WEAK PU	+3VS
GPIO 34	Native	STP_PCI#	EXT PU	+3VS
GPIO 35	Native	SATACLKREQ#	EXT PD	+3VS
GPIO 36	GPO	DGPU_PWR_EN#	EXT PU	+3VS
GPIO 37	GPI	DGPU_PRSENT#	EXT PD	+3VS
GPIO 38	GPI	PCB_ID0	EXT PD	+3VS
GPIO 39	GPI	PCB_ID1	EXT PD	+3VS
GPIO 40	Native	USB_OC2#	EXT PU	+3VSUS
GPIO 41	Native	OC2#	EXT PU (Not used)	+3VSUS
GPIO 42	Native	OC3#	EXT PU (Not used)	+3VSUS
GPIO 43	Native	OC4#	EXT PU (Not used)	+3VSUS
GPIO 44	Native	CLK_REQ5#	EXT PU (Not used)	+3VSUS
GPIO 45	Native	CLK_REQ6#	EXT PU (Not used)	+3VSUS
GPIO 46	Native	CLK_REQ7#	EXT PU (Not used)	+3VSUS
GPIO 47	Native	PECLK_REQ#	EXT PU	+3VSUS
GPIO 48	GPO	-	EXT PU	+3VS
GPIO 49	GPO	PCH_TEMP_EN	EXT PU	+3VS
GPIO 50	Native	PCI_REQ1#	EXT PU (Not used)	+5VS
GPIO 51	Native	PCI_GNT1#	INT PU	+3VS
GPIO 52	GPO	DGPU_SELECT#	EXT PU	+5VS
GPIO 53	GPO	PCI_GNT2#	INT PU	+3VS
GPIO 54	GPO	-	-	+5VS
GPIO 55	Native	PCI_GNT3#	INT PU	+3VS
GPIO 56	Native	CLKREQ2_GLAN#_R	EXT PD	+3VSUS
GPIO 57	GPO	BT_ON	EXT PU(DIODE)	+3VSUS
GPIO 58	Native	SML1_CLK	EXT PU	+3VSUS
GPIO 59	Native	USB_OC01#	EXT PU	+3VSUS
GPIO 60	GPO	-	-	+3VSUS
GPIO 61	Native	PM_SUS_STAT#	-	+3VSUS
GPIO 62	Native	SUS_CLK	-	+3VSUS
GPIO 63	Native	PM_SLP_S5#	-	+3VSUS
GPIO 64	Native	CLK_OUT0	INT TBD	+3VS
GPIO 65	Native	CLK_OUT1	INT TBD	+3VS
GPIO 66	Native	EDID_SELECT#	INT TBD	+3VS
GPIO 67	Native	CLK_OUT3	INT TBD	+3VS
GPIO 72	GPO	PM_BATLOW#	EXT PU (Not used)	+3VSUS
GPIO 73	Native	CLK_REQ0#	EXT PU (Not used)	+3VSUS
GPIO 74	GPO	-	EXT PU (Not used)	+3VSUS
GPIO 75	Native	SML1_DATA	EXT PU	+3VSUS

EC
IT8570

EC GPIO	Use As	Signal Name
GPA0	0	PWR_LED#
GPA1	0	CHG_LED#
GPA2	0	CHG_FULL_LED#
GPA3	-	-
GPA4	0	LCD_BL_PWM
GPA5	0	FAN0_PWM
GPA6	-	-
GPA7	-	-
GPB0	0	BATSEL_0
GPB1	0	BATSEL_1
GPB2	0	ME_AC_PRESENT
GPB3	IO	SMB0_CLK
GPB4	IO	SMB0_DAT
GPB5	0	A20GATE
GPB6	0	KB_RST#
GPB7	0	PM_RSMRST#
GPC0	0	CLK_UC
GPC1	IO	SMB1_CLK
GPC2	IO	SMB1_DAT
GPC3	0	PM_PWRBTN#
GPC4	I	AC_IN_OC#
GPC5	0	OP_SD#
GPC6	I	BAT1_IN_OC#
GPC7	-	-
GPD0	-	-
GPD1	I	PM_SUSC#
GPD2	I	BUF_PLT_RST#
GPD3	0	EC_SCI#
GPD4	0	EC_SMI#
GPD5	0	LCD_BACKOFF#
GPD6	I	FAN0_TACH
GPD7	I	HDMI_HPD
GPE0	-	-
GPE1	-	-
GPE2	-	-
GPE3	-	-
GPE4	I	PWR_SW#
GPE5	-	-
GPE6	I	LID_SW#
GPE7	-	-
GPF0	-	-
GPF1	0	VSUS_ON
GPF2	0	VTT_DRAM_PWR_SEL1
GPF3	0	VTT_DRAM_PWR_SEL2
GPF4	IO	TP_CLK
GPF5	IO	TP_DAT
GPF6	0	THRO_CPU
GPF7	0	PCH_SPI_OV
GPG0	I	ME_SusPwrDnAck_EC
PGP1	I	PM_USB#
GGP2	-	-
GGP6	-	-
GPH0	IO	PM_CLKRUN#
GPH1	0	VGA_DEEPIPLE (TBD)
GPH2	0	CHG_EN
GPH3	0	SUSC_EC#
GPH4	0	SUSB_EC#
GPH5	-	-
GPH6	0	CAP_LED#
GPI0	I	GPU_ALERT#
GPI1	I	SUS_PWRGD
GPI2	I	ALL_SYSTEM_PWRGD
GPI3	I	VRM_PWRGD
GPI4	I	PCH_TEMP_ENABLE
GPI5	I	CPU_VCORE_I_SEN
GPI6	I	DGPU_VCORE_I_SEN
GPI7	-	-
GPJ0	0	CPU_VRON
GPJ1	0	PM_PWROK
GPJ2	0	VSET_EC
GPJ3	0	ISET_EC
GPJ4	0	V_DA_EC/VCORE_SEL1
GPJ5	0	VCORE_SEL2

SM_BUS ADDRESS :

PCH Master		
SM-Bus Device	SM-Bus Address	
Clock Generator(ICS9LV53162)	1101001x (D2)	
SO-DIMM 0	1010000x (A0)	
SO-DIMM 1	1010001x (A4)	
WiFi/WiMax	N/A	
EC Master (SMB1)		
SM-Bus Device	SM-Bus Address	
VGA Thermal IC(G781-1)	1001101x (9A)	

PCIE 1	
PCIE 2	Minicard WLAN
PCIE 3	
PCIE 4	USB 3.0
PCIE 5	
PCIE 6	GLAN
PCIE 7	
PCIE 8	

USB 0	USB Port (1)
USB 1	USB Port (2)
USB 2	USB Port (3)
USB 3	
USB 4	
USB 5	
USB 6	
USB 7	
USB 8	WLAN
USB 9	CMOS Camera
USB 10	
USB 11	
USB 12	Bluetooth
USB 13	

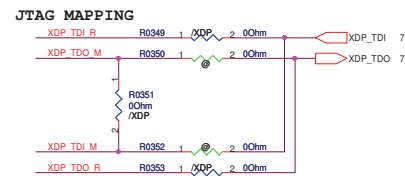
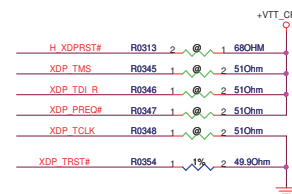
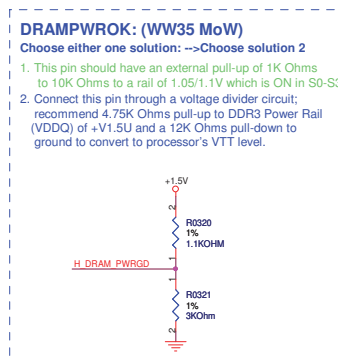
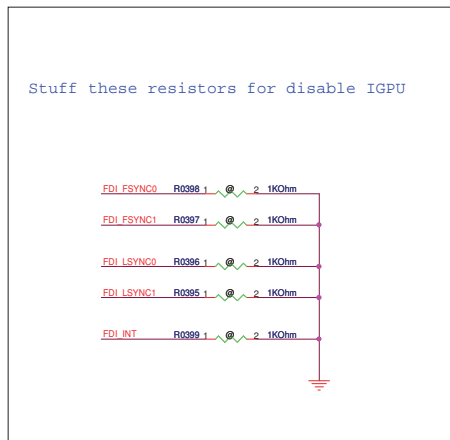
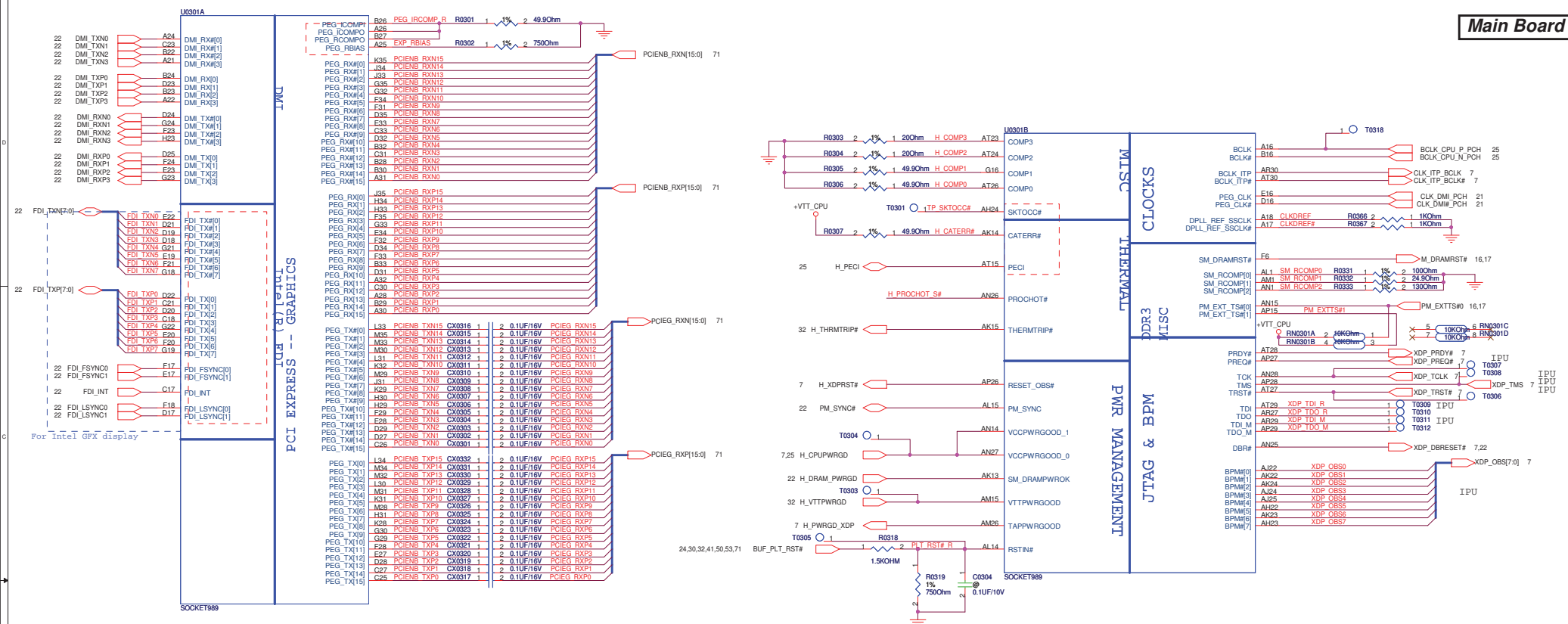
SATA 0	SATA HDD (1)
SATA1	SATA ODD

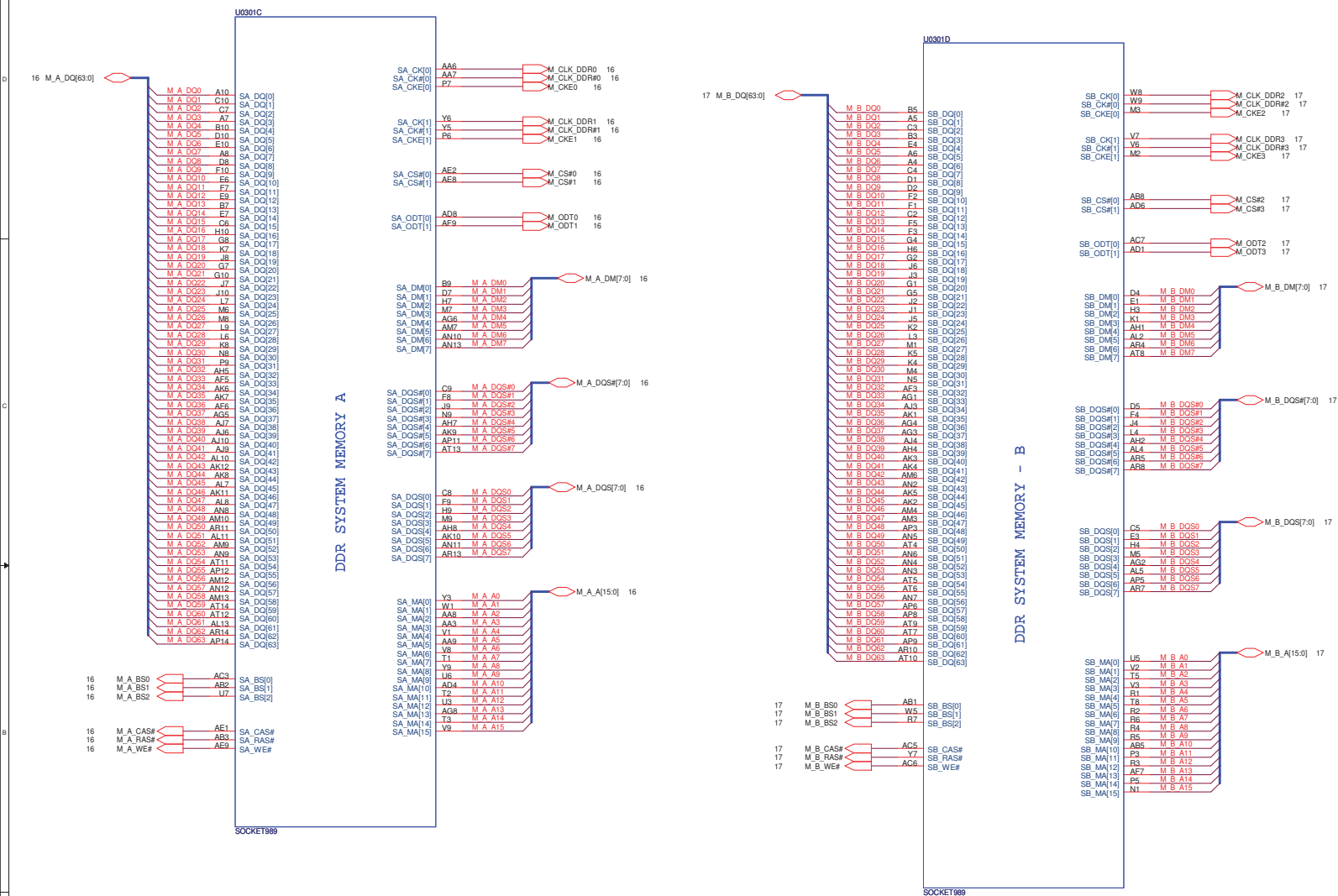
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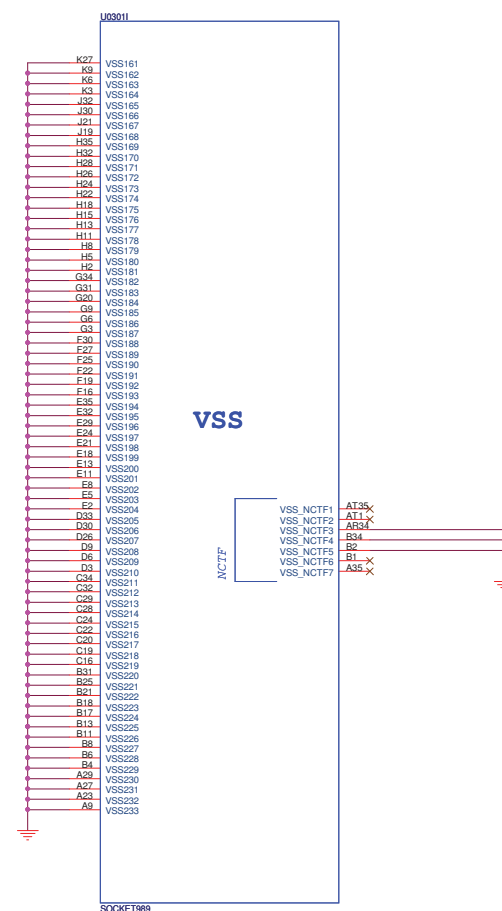
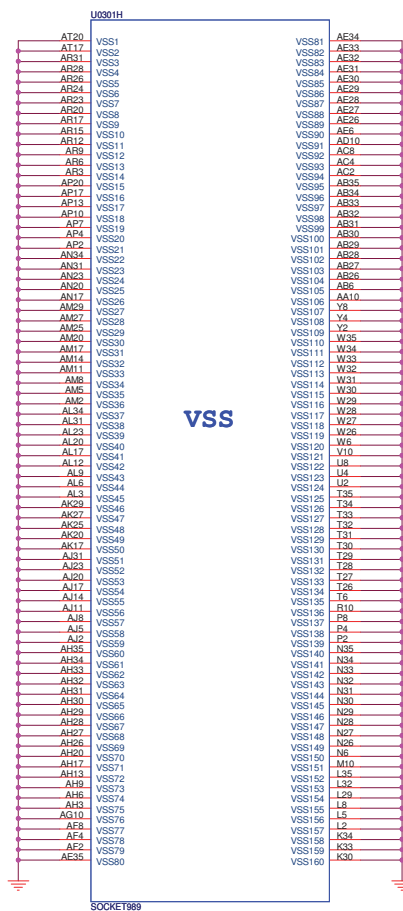
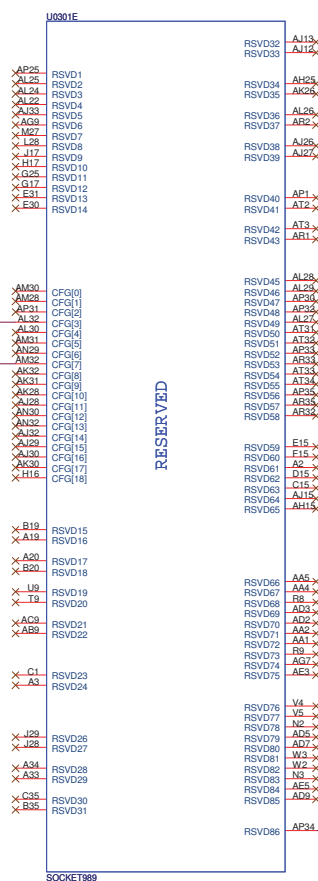
ASUSTek COMPUTER INC. NDAEngineer: JAY TSAI

SizeCProject NameK42JvRev1.01

Date: Thursday, February 11, 2010Sheet2 of 95







CFG strapping information:

CFG[1:0]: PCI Express Port Bifurcation:(Clarksfield Only)
 - 11 = 1 x 16 PEG (Default)
 - 10 = 2 x 8 PEG

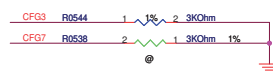
CFG[3]: PCIe Static Numbering Lane Reversal.(Arrandale Only)
 - 1:Normal Operation (Default)
 - 0:Lane Numbers Reversed 15 -> 0, 14 -> 1, ...

CFG[4]: Embedded DisplayPort Detection (Arrandale Only)
 - 1: Disabled - No Physical Display Port attached to Embedded DisplayPort
 - 0: Enabled - An external Display Port device is connected to the Embedded Display Port

CFG[7]: Fixed for PCI Express 2.0 jitter specifications.(Clarksfield)
Clarksfield (only for early samples pre-ES1) - Connect to GND with 3.01K Ohm/5% resistor
For a common motherboard design (for AUB and CFD),
the pull-down resistor should be used. Does not impact Arrandale functionality.

Note: (Auburndale)Hardware Straps are sampled on the asserting edge of VCCPWRGOOD_0 and VCCPWRGOOD_1 and latched inside the processor.

Note: (Clarksfield)Hardware Straps are sampled after RSTIN# de-assertion.



CFG strapping information:

For Arrandale

CFG[2:0] - Reserved configuration pins. Test points may be placed on these pins on a common motherboard design.

CFG[3] – PCI Express* Static Lane Numbering Reversal. Lane Reversal will be applied across all 16 Lanes.

- 1: No lane reversal
- 0: Reversal

CFG[4] - Embedded DisplayPort Detection:
This is used to detect the presence of a device on the Embedded DisplayPort.

CFG[17:5] - Reserved configuration pin

Note: Hardware straps are sampled on the asserting edge of VCCPWRGOOD_0 and VCCPWRGOOD_1 and latched inside the processor.

For Clarksfield

CFG[1:0] - PCI Express* Port Bifucation:

- 11 = 1 x16 PEG
- 10 = 2 x8 PEG

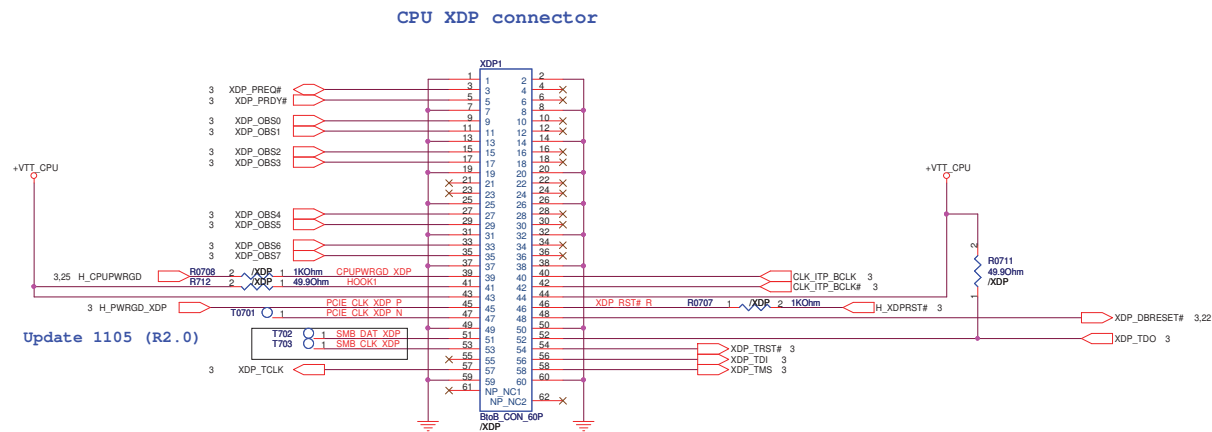
CFG[2] - Reserved Configuration pin.

CFG[3] – Reserved (Used by Arrandale Pprocessors for PCI Express* Static Lane Numbering Reversal)


CFG[11:4] - Reserved configuration pins.

CFG[17:13] - Reserved configuration pins.

Note: Hardware straps are sampled after RSTIN# de-assertion.








Title : NB ****

ASUSTeK COMPUTER INC. NB1Engineer:

Size	Project Name	Rev
Custom	K42Jv	1.01

Date: Thursday, February 11, 2010Sheet 10 of 96






Title : NB ****

ASUSTeK COMPUTER INC. NB1Engineer:

Size	Project Name	Rev
Custom	K42Jv	1.01

Date: Thursday, February 11, 2010Sheet 12 of 96

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C						C
B						B
A						A
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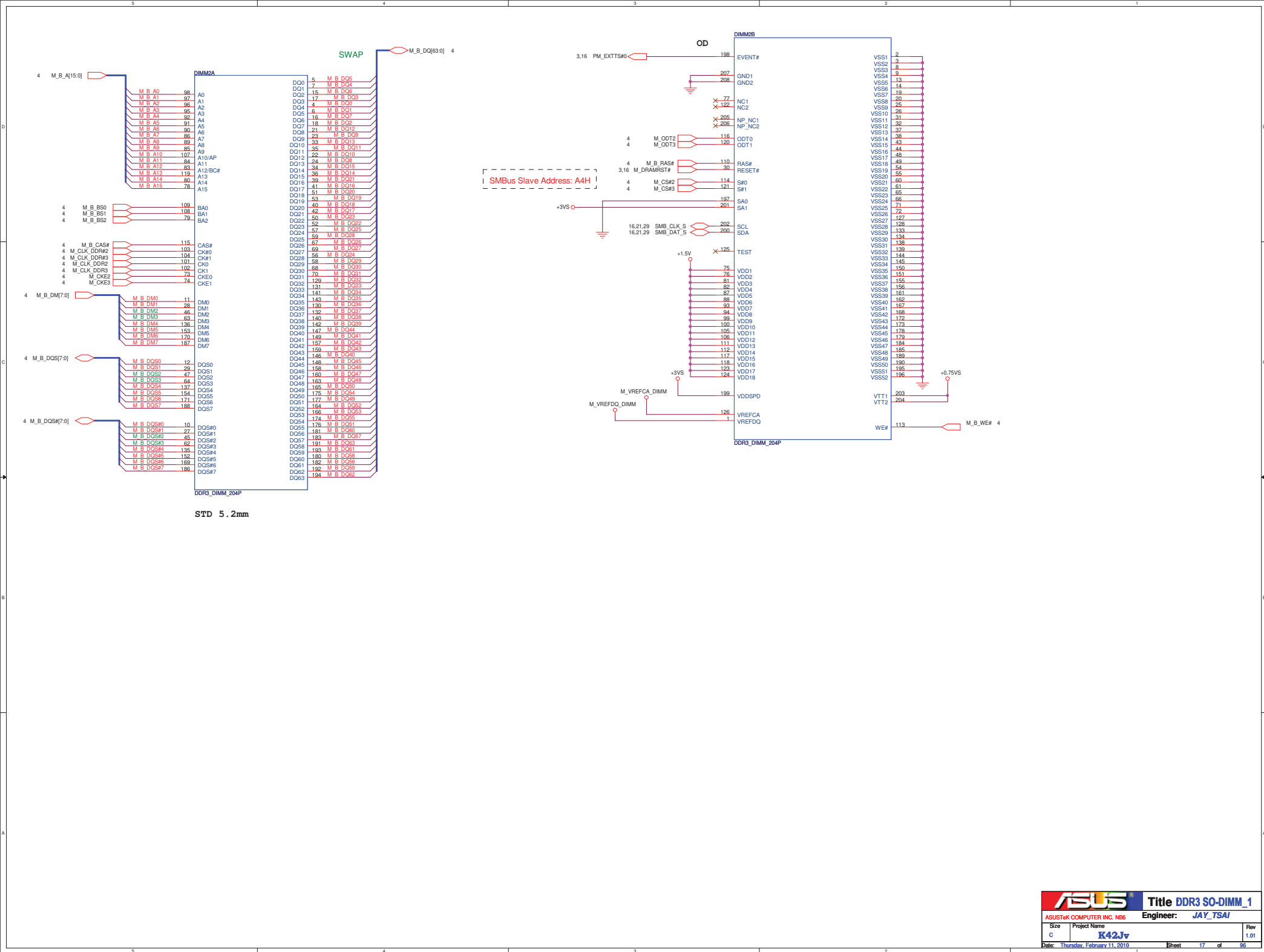


Table 2-28. Functional Strap Definitions (Sheet 1 of 5)

Signal	Usage	When Sampled	Comment
SPKR	No Reboot	Rising edge of PWROK	The signal has a weak internal pull-down. Note: the internal pull-down is disabled after PLTRST# de-asserts. If the signal is sampled high, this indicates that the system is strapped to the "No Reboot" mode (the PCH will disable the TCO Timer system reboot feature). The status of this strap is readable using the NO_REBOOT bit (Chipset Config Registers: Offset 3410h:bit 5).
INT3_V#	Reserved	Rising edge of PWROK	This signal has a weak internal pull up. Note: the internal pull-up is disabled after PLTRST# de-asserts. NOTE: This signal should not be pulled low.
GNT[3]# / GPIO[55]	Top-Block Swap Override	Rising edge of PWROK	The signal has a weak internal pull-up. Note: the internal pull-up is disabled after PCIRST# de-asserts. If the signal is sampled low, this indicates that the system is strapped to the "topblock swap" mode (the PCH inverts ALG for all cycles targeting BIOS space). The status of this strap is readable using the Top Swap bit (Chipset Config Registers: Offset 3414h:bit 0). Note that software will not be able to clear the Top-Swap bit until the system is rebooted without GNT3# being pulled down.
INTVRMEN	Integrated 1.05 V VRM Enable / Disable	Always	Integrated 1.05 V VRMs is enabled when high. NOTE: This signal should always be pulled high

Table 2-28. Functional Strap Definitions (Sheet 2 of 5)

Signal	Usage	When Sampled	Comment															
			<p>This signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts.</p> <p>This field determines the destination of accesses to the BIOS memory range. Also, controllable using Boot BIOS Destination bit (Chipset Config Registers: Offset 3410h:bit 11). This strap is used in conjunction with Boot BIOS Destination Selection 0 strap.</p> <table><tr><th>Bit11</th><th>Bit 10</th><th>Boot BIOS Destination</th></tr><tr><td>0</td><td>1</td><td>Reserved</td></tr><tr><td>1</td><td>0</td><td>PCI</td></tr><tr><td>1</td><td>1</td><td>SPI</td></tr><tr><td>0</td><td>0</td><td>LPC</td></tr></table> <p>NOTE: If option 00 LPC is selected, BIOS may still be placed on LPC; however, all platforms with the PCH require SPI flash connected directly to the PCH SPI bus with a valid descriptor in order to boot.</p> <p>NOTE: Booting to PCI is intended for debug/testing only. Boot BIOS Destination Select to LPC/PCI by functional strap or using Boot BIOS Destination Bit will not affect SPI accesses initiated by Intel® Management Engine or Integrated GbE LAN.</p>	Bit11	Bit 10	Boot BIOS Destination	0	1	Reserved	1	0	PCI	1	1	SPI	0	0	LPC
Bit11	Bit 10	Boot BIOS Destination																
0	1	Reserved																
1	0	PCI																
1	1	SPI																
0	0	LPC																
GNT1# / GPIO51	Boot BIOS Strap bit [1] BBS[1]	Rising edge of PWROK																

Table 2-28. Functional Strap Definitions (Sheet 5 of 5)

Signal	Usage	When Sampled	Comment
SDVO_CTRLDA TA	Digital Display Port (Port B)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port B is enabled when sampled high. When sampled low Port B is Disabled.
DDPC_CTRLDA TA	Digital Display Port (Port C)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port C is enabled when sampled high. When sampled low Port C is Disabled.
DDPD_CTRLDA TA	Digital Display Port (Port D)	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. Port D is enabled when sampled high. When sampled low Port D is Disabled.

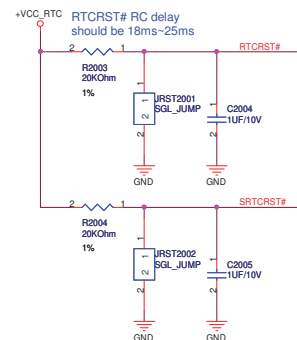
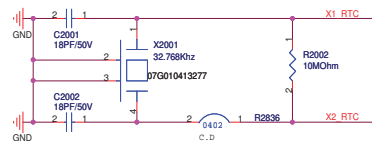
Table 2-28. Functional Strap Definitions (Sheet 3 of 5)

Signal	Usage	When Sampled	Comment															
GNT[0]#	Boot BIOS Strap bit[0] BBS[0]	Rising edge of PWROK	<p>This Signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts.</p> <p>This field determines the destination of accesses to the BIOS memory range. Also, controllable using Boot BIOS Destination bit (Chipset Config Registers:Offset 3410h:bit 10). This strap is used in conjunction with Boot BIOS Destination Selection 1 strap.</p> <table><thead><tr><th>Bit11</th><th>Bit 10</th><th>Boot BIOS Destination</th></tr></thead><tbody><tr><td>0</td><td>1</td><td>Reserved</td></tr><tr><td>1</td><td>0</td><td>PCI</td></tr><tr><td>1</td><td>1</td><td>SPI</td></tr><tr><td>0</td><td>0</td><td>LPC</td></tr></tbody></table> <p>NOTE: If option 00 LPC is selected, BIOS may still be placed on LPC; however, all platforms with the PCH require SPI flash connected directly to the PCH's SPI bus with a valid descriptor in order to boot.</p> <p>NOTE: Booting to PCI is intended for debug/testing only. Boot BIOS Destination Select to LPC/PCI by functional strap or using Boot BIOS Destination Bit will not affect SPI accesses initiated by Management Engine or Integrated GbE LAN.</p>	Bit11	Bit 10	Boot BIOS Destination	0	1	Reserved	1	0	PCI	1	1	SPI	0	0	LPC
Bit11	Bit 10	Boot BIOS Destination																
0	1	Reserved																
1	0	PCI																
1	1	SPI																
0	0	LPC																
GNT2# / GPIO53	ESI Strap (Server Only)	Rising edge of PWROK	<p>This Signal has a weak internal pull-up. Note that the internal pull-up is disabled after PCIRST# de-asserts.</p> <p>Tying this strap low configures DMI for ESI compatible operation.</p> <p>NOTE: ESI compatible mode is for server platforms only. This signal should not be pulled low for desktop and mobile.</p>															
NV_ALE	Reserved	Rising edge of PWROK	<p>This signal has a weak internal pull down.</p> <p>NOTE: This signal should not be pulled high</p>															

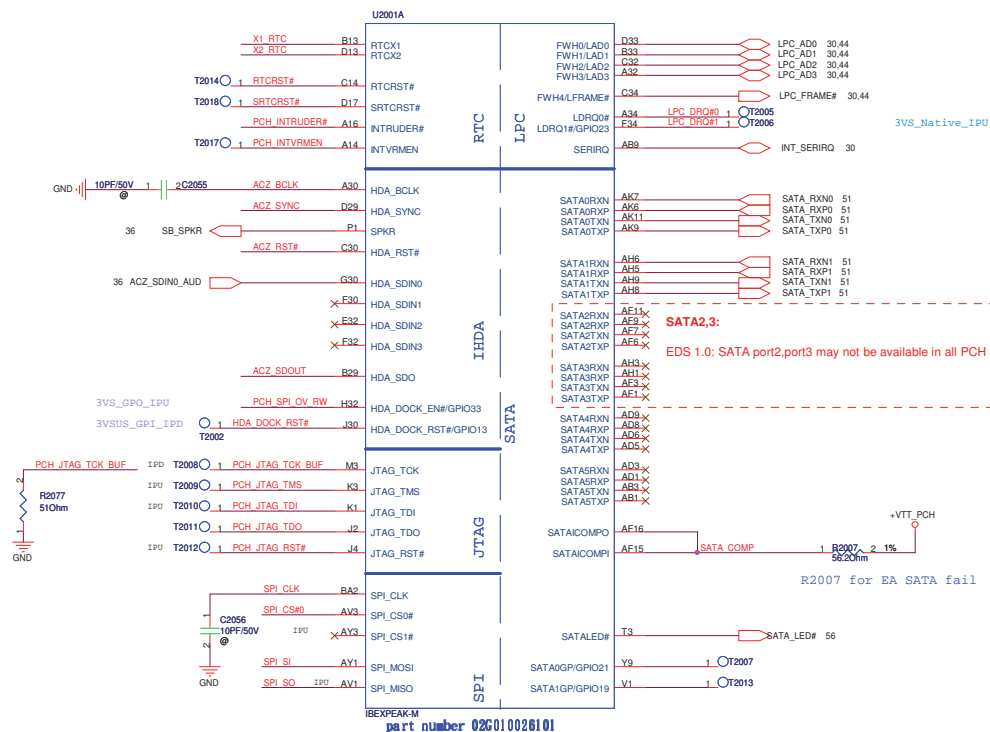
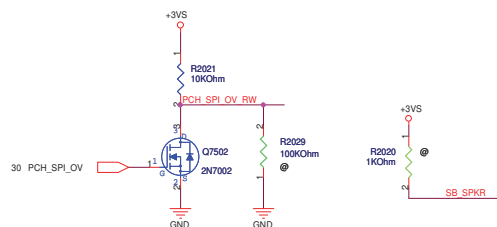
Table 2-28. Functional Strap Definitions (Sheet 4 of 5)

Signal	Usage	When Sampled	Comment
HDA_DOCK_EN# / GPIO[33]	Flash Descriptor Security Override/ ME Debug Mode	Rising edge of PWROK	Signal has a weak internal pull-up. If strap is sampled high, the security measures defined in the Flash Descriptor will be in effect (default). If sampled low, the Flash Descriptor Security will be overridden. This strap should only be asserted low using external pull down in manufacturing/ debug environments ONLY. NOTE: Asserting the GPIO33 low on the rising edge of PWROK will also halt Intel® Management Engine after chipset bringup and disable runtime Intel® Management Engine features. This is a debug mode and must not be asserted after manufacturing/debug.
SPI_MOSI	TPM Functionality Disable	Rising edge of MEPWROK	This signal has a weak internal pull-down resistor. This signal must be sampled low.
NV_CLE	DMI Termination Voltage	Rising edge of PWROK	This signal has a weak internal pull-down.
HDA_SDO	Reserved	Rising edge of RSMRST#	This signal has a weak internal pull down. NOTE: This signal should not be pulled high
GPIO8	Reserved	Rising edge of RSMRST#	This signal has a weak internal pull up. Note that the weak internal pull-up is disabled after RSMRST# de-asserts. NOTE: This signal should not be pulled low
GPIO27	Reserved	Rising edge of RSMRST# pin	This signal should be left as a No Connect.
HDA_SYNC	On-Die PLL Voltage Regulator Voltage Select	Rising edge of RSMRST# pin	This signal has a weak internal pull down. On-Die PLL VR is supplied by 1.5 V when sampled high; 1.8 V when sampled low.
GPIO15	Reserved	Rising edge of RSMRST# pin	Low = Intel® Management Engine Crypto Transport Layer Security (TLS) cipher suite with no confidentiality High = Intel® Management Engine Crypto TLS cipher suite with confidentiality This signal has a weak internal pull down. NOTE: A strong pull up may be needed for GPIO functionality
L_DDC_DATA	LVDS	Rising Edge of PWROK	This signal has a weak internal pull-down. Note that the weak internal pull-down is disabled after PLTRST# de-asserts. LVDS is enabled when sampled high. When sampled low LVDS is Disabled.

<i>CMOS Settings</i>	<i>JRST2001</i>	<i>TPM Settings</i>	<i>JRST2002</i>
<i>Clear CMOS</i>	<i>Shunt</i>	<i>Clear ME RTC Registers</i>	<i>Shunt</i>
<i>Keep CMOS</i>	<i>Open (Default)</i>	<i>Keep ME RTC Registers</i>	<i>Open (Default)</i>



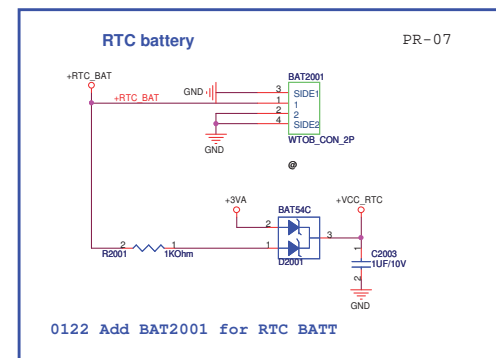
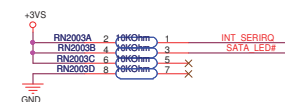
Strap information:		
	H	L
AC95VDD: Select VCCVDD 1.5V or 1.8V (IPD)	1.5V	1.8V
SB_SFRX: No reboot strap (IPD)	No reboot	Disable No reboot
FSH_SPI_OV_EN: (IPU)	No Flash Me FW	Flash Me FW
SPI_SI: ITPM strap. (IPD)	Enable	Disable
FSH_INTVDD: Integrated 1.05 V VDD Enable /Disable	Enable	Disable

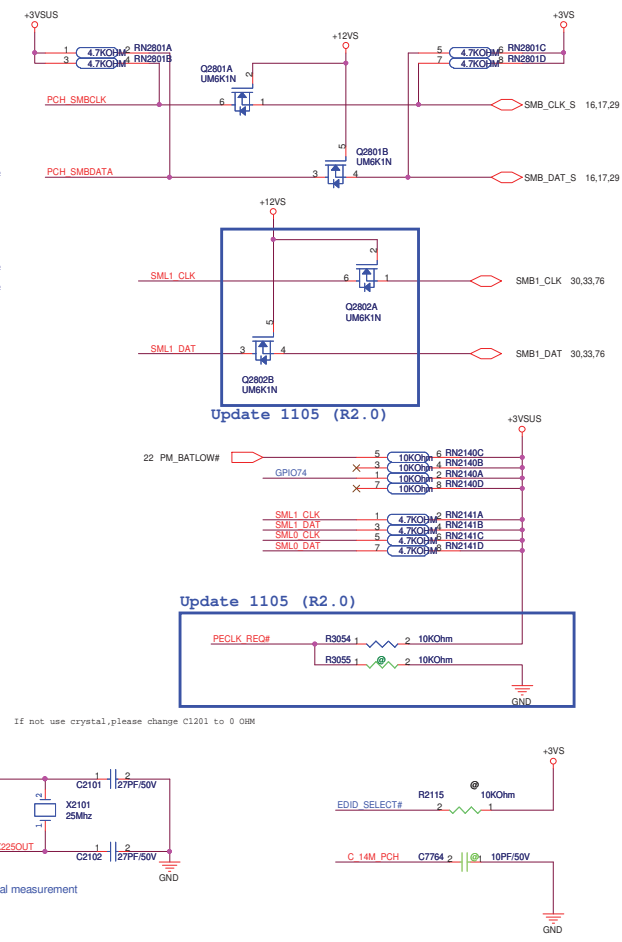
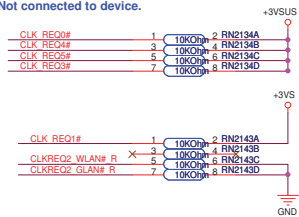


PCH SPI ROM

The diagram illustrates the PCH SPI ROM circuit. Key components and connections include:

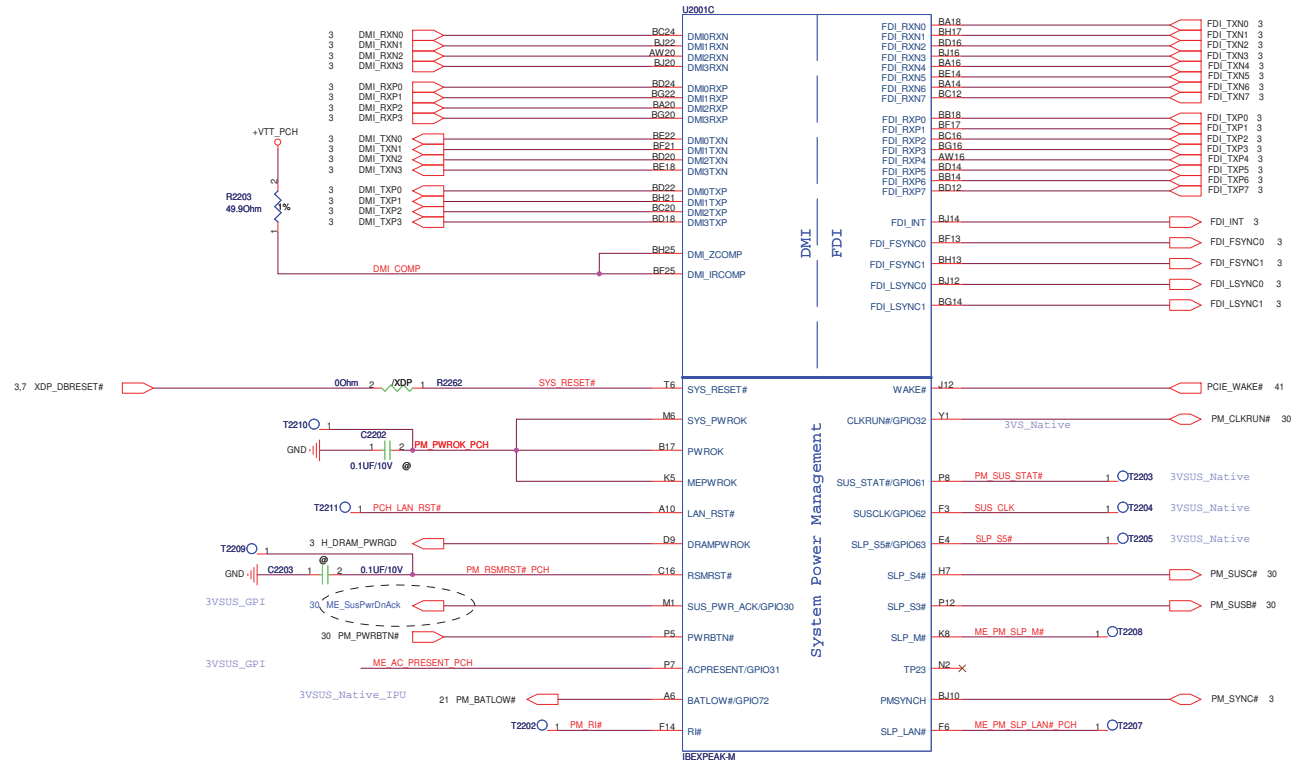
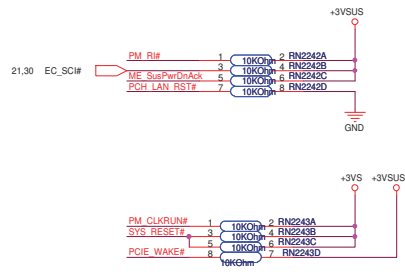
- Power Supply:** +3V_EC, +3V_SVS, and +3V_SPI.
- Resistors:** R2831, R2832, R2833, R2843A, R2843B, R2837, R2834, and R2835.
- Capacitors:** C402 and C2802 (0.1uF/16V).
- Header:** J2001 (Debug Conn.) with pins for EC SPI CE#, SPI SIO PCH, and EC SPI BI.
- ICs:** MX25L3206DM2-12G (32Mb) SPI ROM and U2801.
- Connections:** The PCH is connected to the EC SPI CE# and SPI SIO signals. The SPI ROM is connected to the PCH via CS#, SO#/SI0, WP#/ACC, GND, VCC, HOLD#, EC SPI CK, and EC SPI DI.





WW35 Update: Integrated Graphics platforms that use only LVDS and/or VGA Displays may use Buffer Through Mode (BTM) and leave 25-MHz crystal and RC components unstuffed

pre-ES1 not support
Reversal Feature



R1.1,item L15

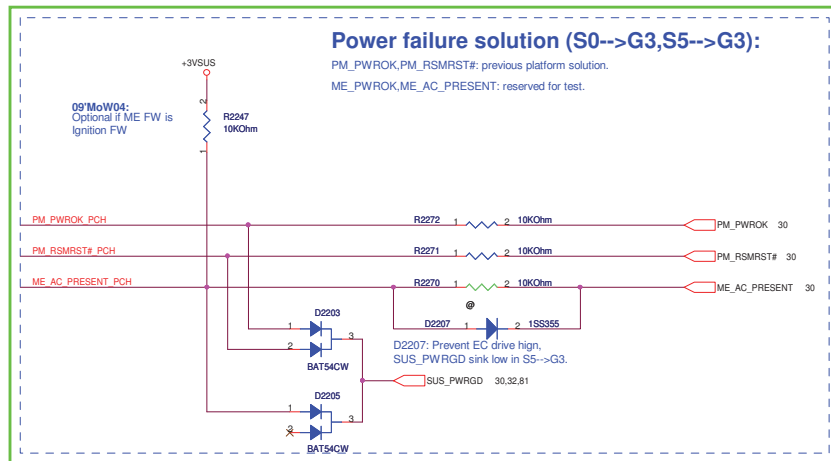


Table 112. Intel ME-EC Interaction Signal List with and without M3 Support

Signal Name	Platform with M3 Support (e.g., Intel® AMT)	Platform without M3 Support (e.g., Intel® ME Ignition Firmware)
SUS_PWR_DN_ACK (GPIO30)	Required	Required
ACPRESENT (GPIO31)	Required	Required Note: Optional if Intel ME FW is Intel® ME Ignition Firmware
SLP_M#	Required	Optional (Tie to SLP_S3#) Note: If SLP_S3# is not routed from PCH to EC, then SLP_M# becomes required from Intel® ME-EC perspective.
SLP_S3#	Optional	Required Note: If SLP_M# is routed from PCH to EC, then SLP_S3# can be optional from Intel ME-EC perspective

NOTE: Optional means that these signals are optional from Intel ME-EC interaction point of view. However, they are platform critical signals and are still required to be routed on the platform.

ME Ignition Firmware is for 2MB SPI core, only PM55 can support on it.

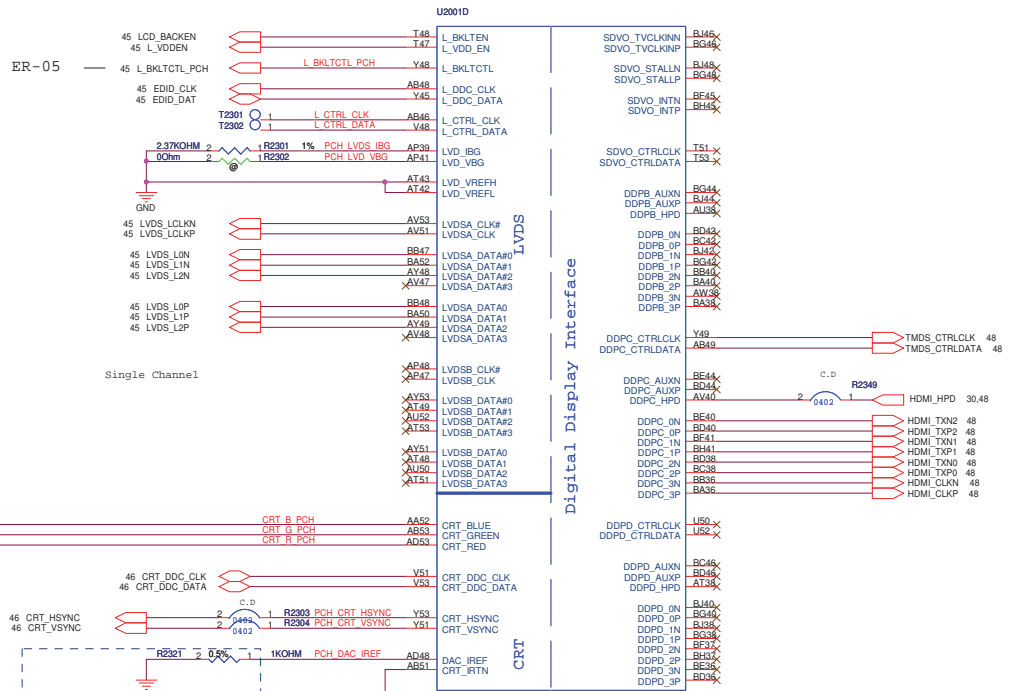


ER-05

LVDS Disable: (For discrete graphic)

1. NC:
 LVDSA_DATA [3:0], LVDSA_DATA# [3:0],
 LVDSA_CLK, LVDSA_CLK#, LVDSB_DATA [3:0],
 LVDSB_DATA# [3:0], LVDSB_CLK, LVDSB_CLK#
 L_VDD_EN, L_BKLTEN, L_BKLTCTL, LVD_VREFH
 LVD_VREFL, LVD_IBG, LVD_VBG

2. Connected to GND:
 VccALVDS, VccTX_LVDS



CRB R0.9,DG R0.8: 1K+/-0.5%

Intel checklist recommend:
 1.02K PD resistor to 0.5%

CRT Disable: (For discrete graphic)

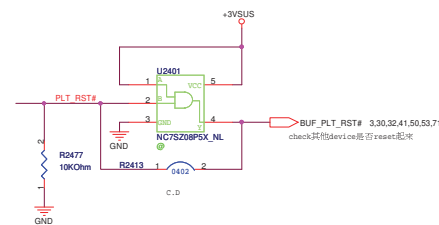
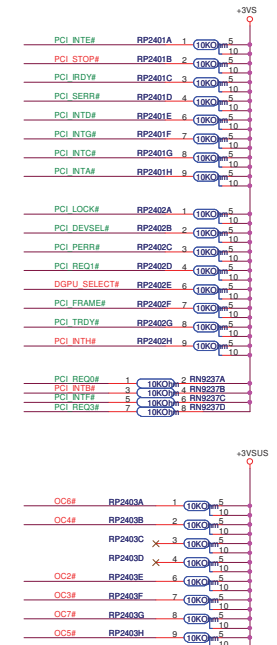
1. NC:
 CRT_RED,CRT_GREEN,CRT_BLUE
 CRT_HSYCN,CRT_VSYN

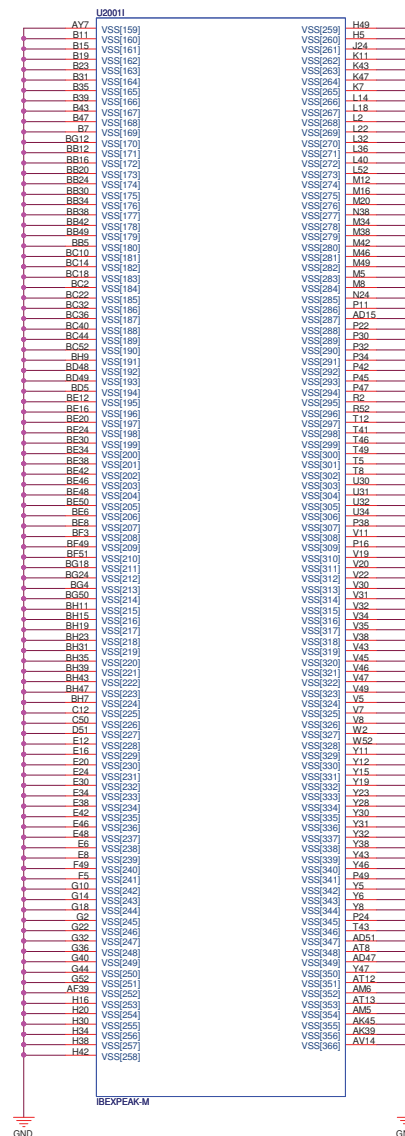
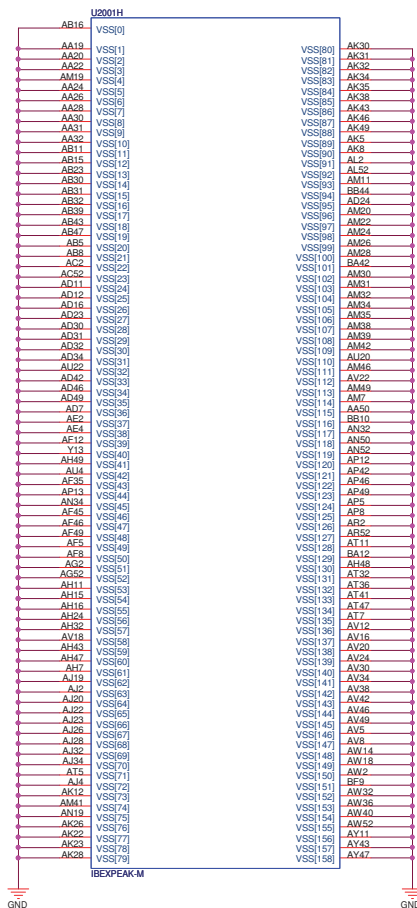
2. 1-kΩ ±0.5% pull-down to GND:
 DAC_IREF

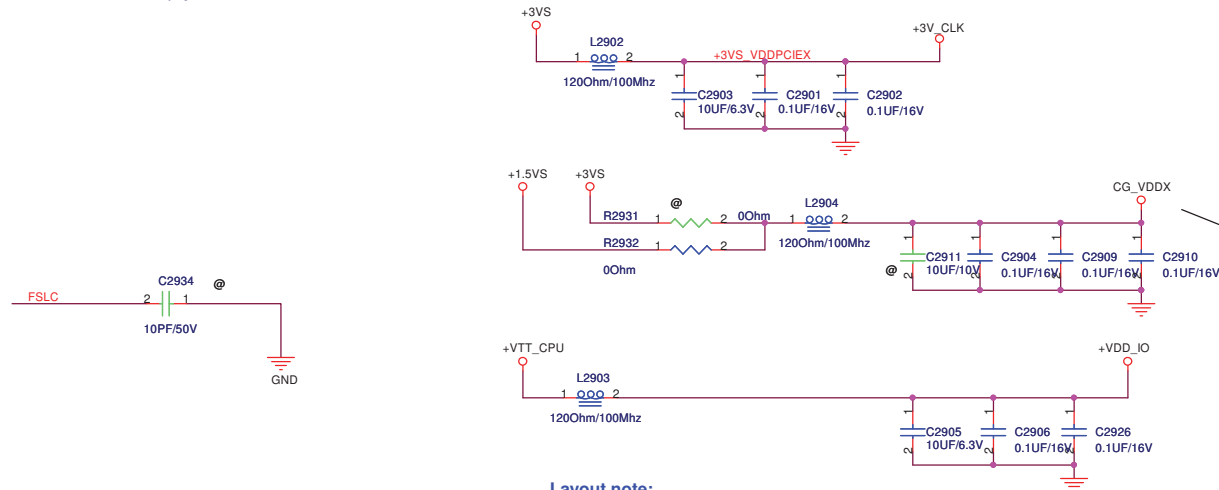
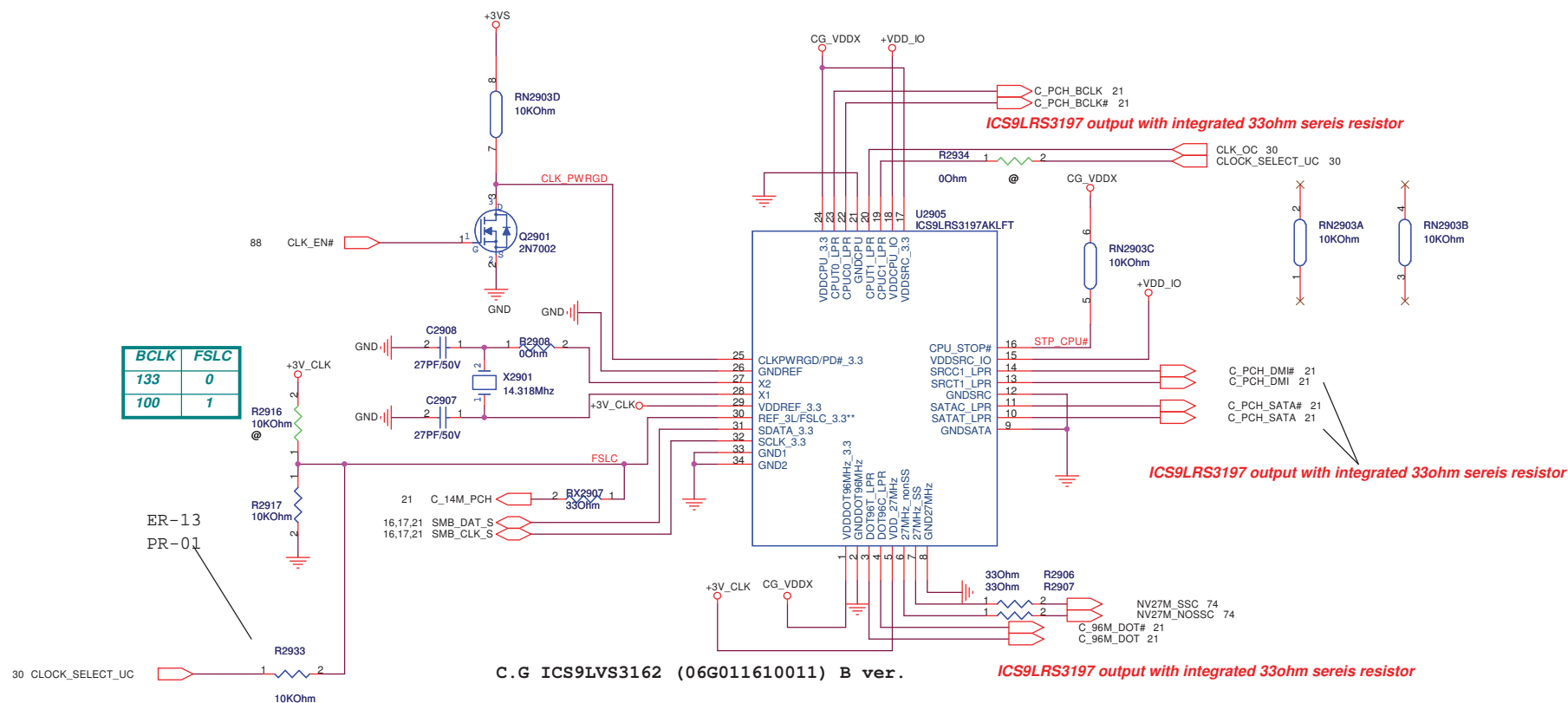
3. Connected to GND:
 CRT_ITRN

4. Connect to +V3.3:
 VCCADAC





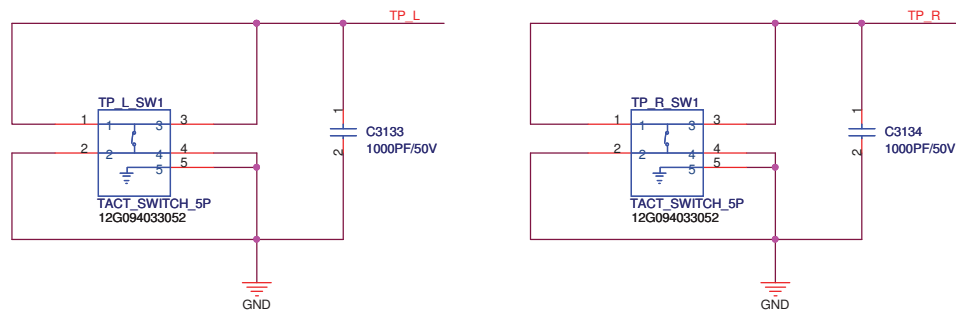




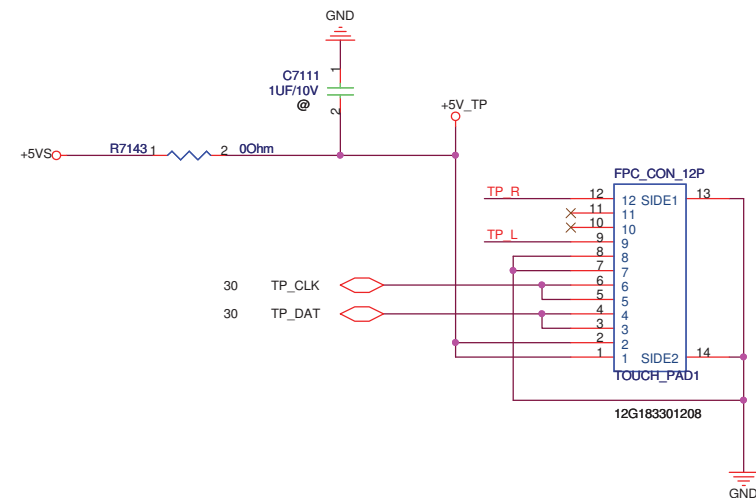
Layout note:
VDD_3.3: 5pin -->0.1uF to each pin
VDD_IO : 2pin -->0.1uF to each pin

<Variant Name>

TouchPad

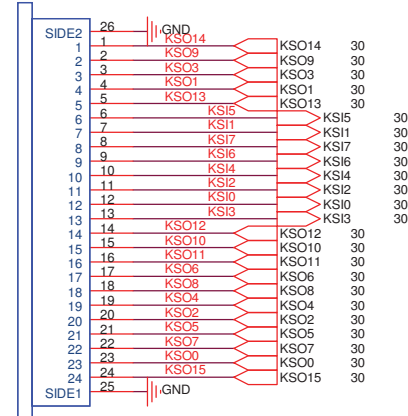


1.0 EMI test need mount C3133 and C3134



Keyboard Connector

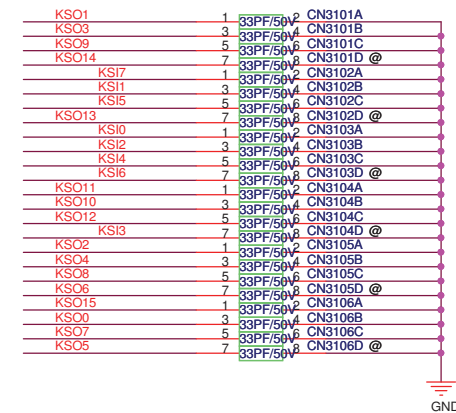
KB_CON1



FPC_CON_24P

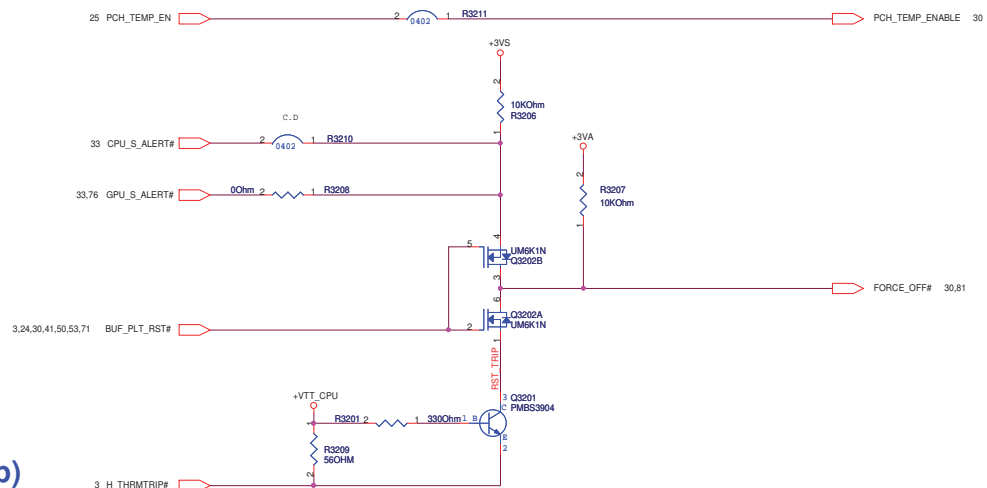
12G182102402

EMI Request



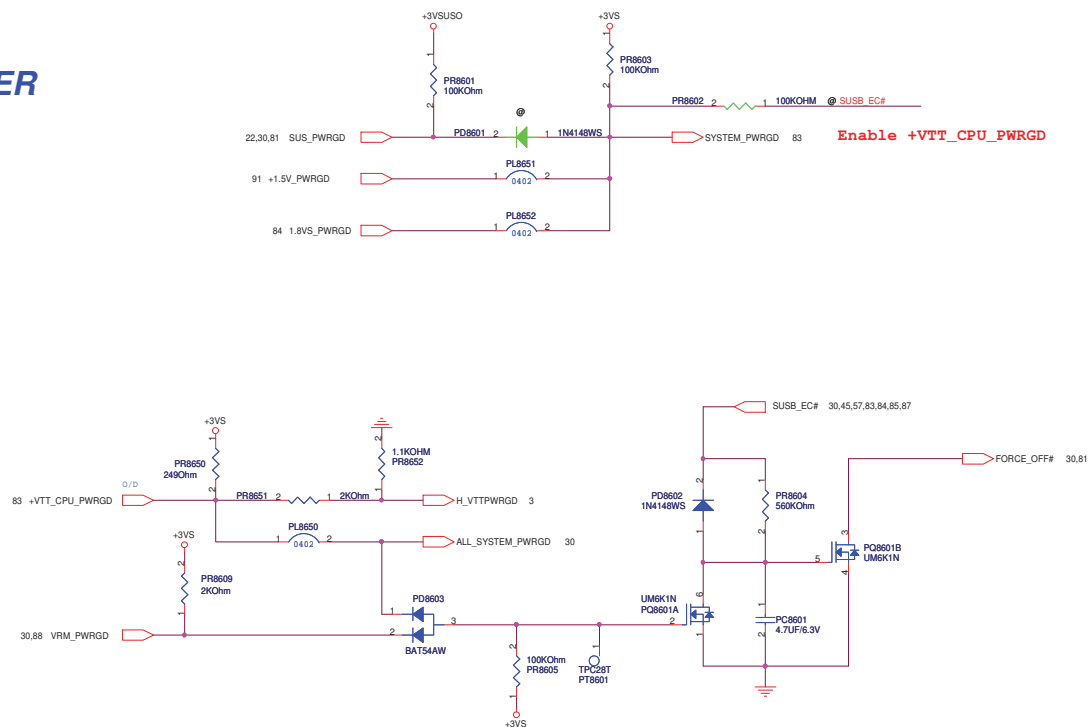
<Variant Name>

Thermal Policy

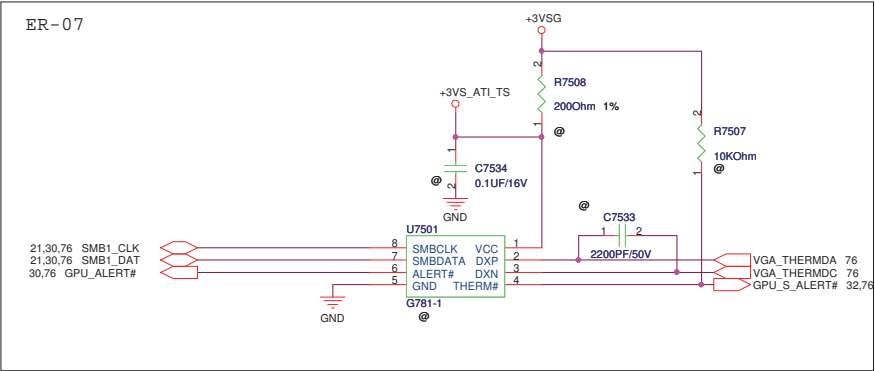


Output (shut down)

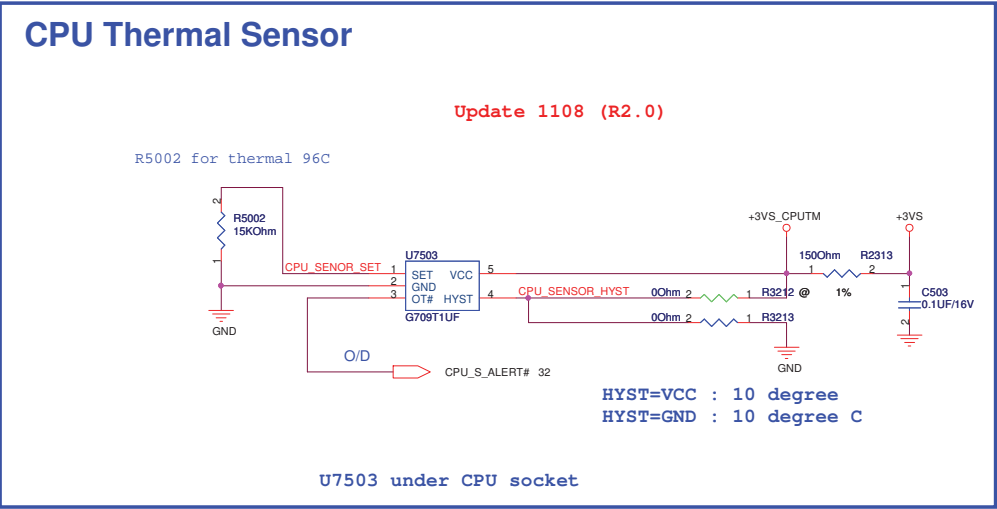
POWER GOOD DETECTOR



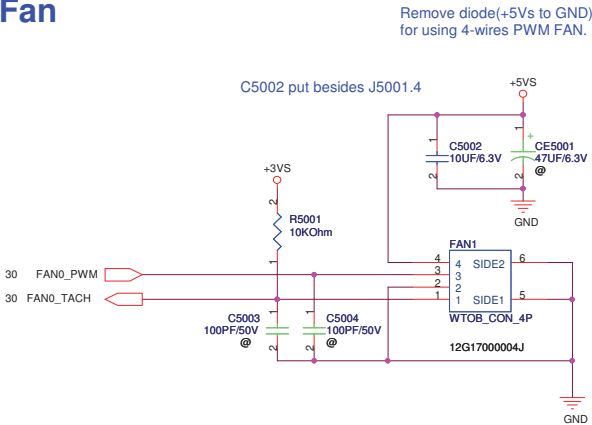
GPU Thermal Sensor




CPU Thermal Sensor

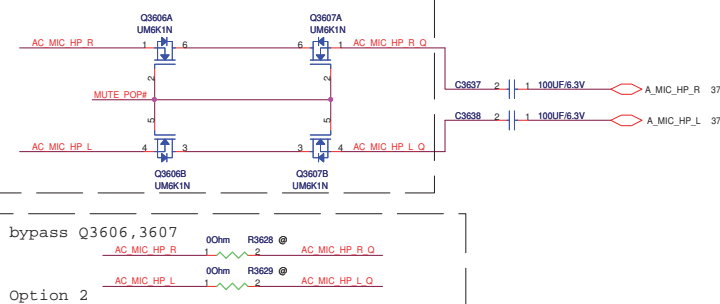
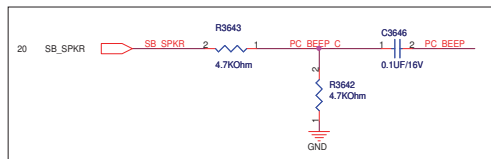
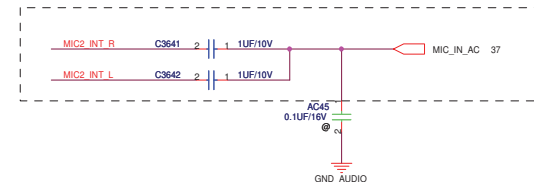
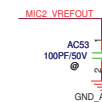
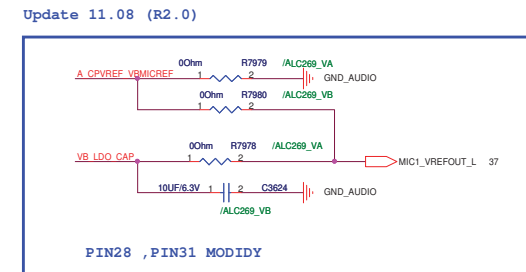
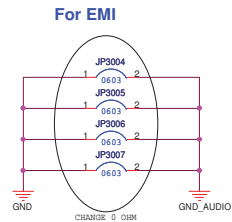
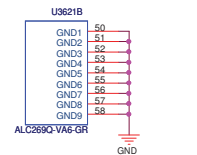
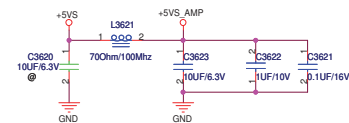


PWM Fan

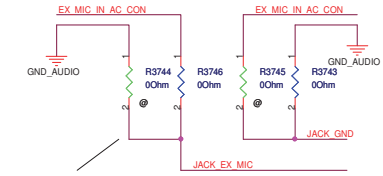
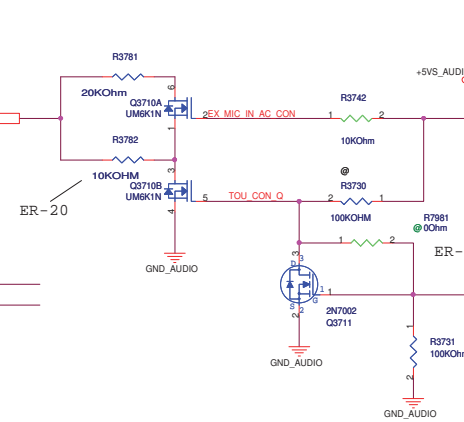
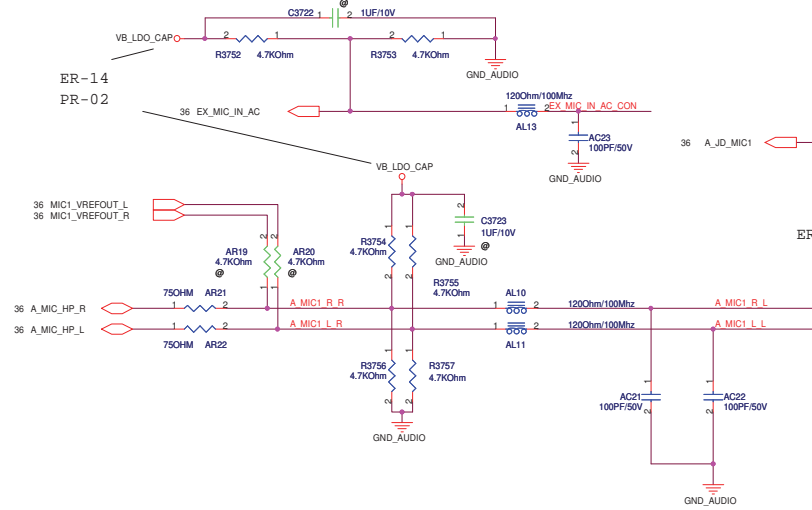
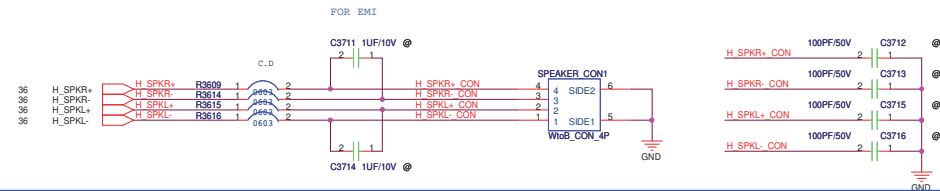


5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

<Variant Name>				
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ASUSTeK COMPUTER INC		Engineer:		
Size	Project Name			Rev
Custom	K42Jv			108
Date:	Thursday, February 11, 2010		Sheet	34 of 96

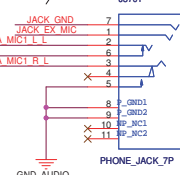


SPEAKER



For 4 ring headset device:
 GMRL:mount R3746,R3743
 MGRL:mount R3744,R3745

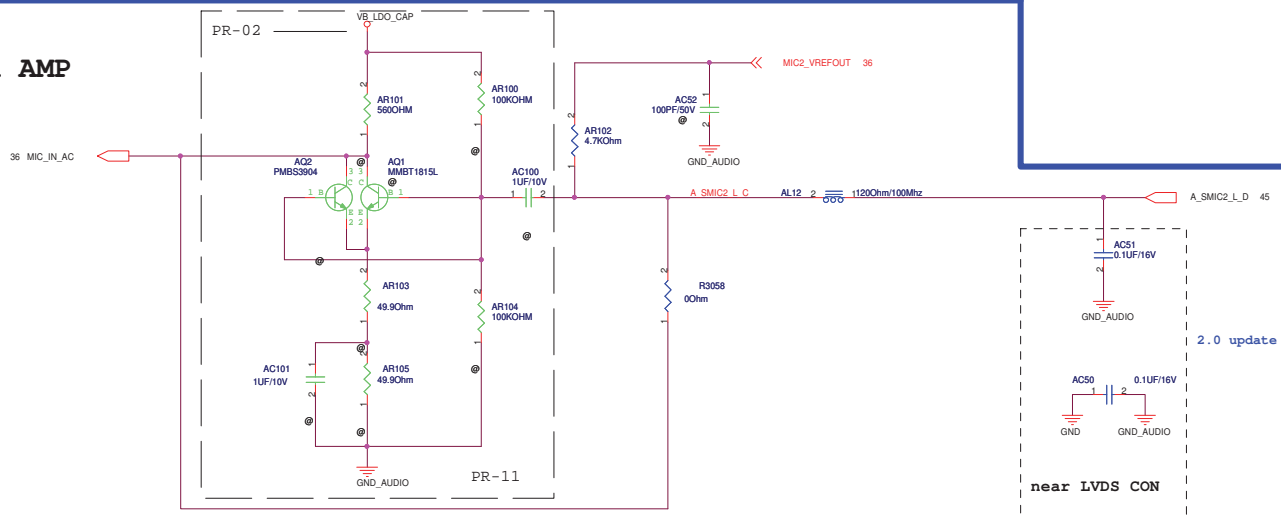
MGRL device must change PHONE JACK,when you use.




ASUS PN : 12G140011074

HP and MIC


Internal MIC and AMP

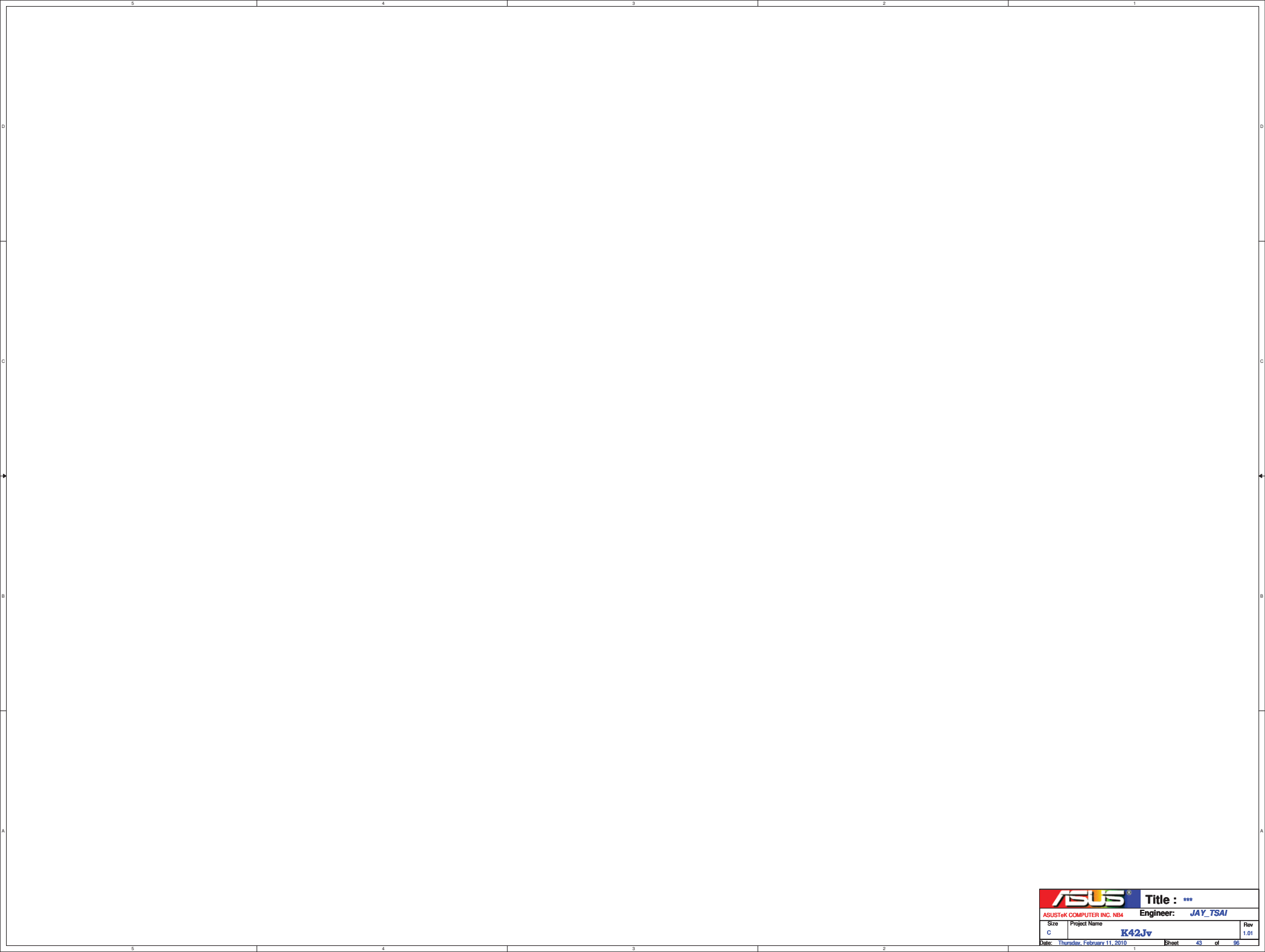





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ASUSTek Computer Inc.			Engineer: JAY_TSAI		
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A3	K42Jv				1.0G
Date: Thursday, February 11, 2010		Sheet	40	of	96

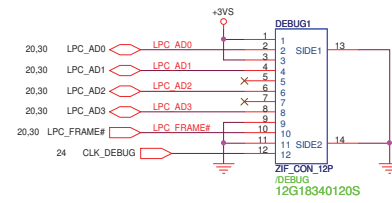
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C				C
B				B
A				A

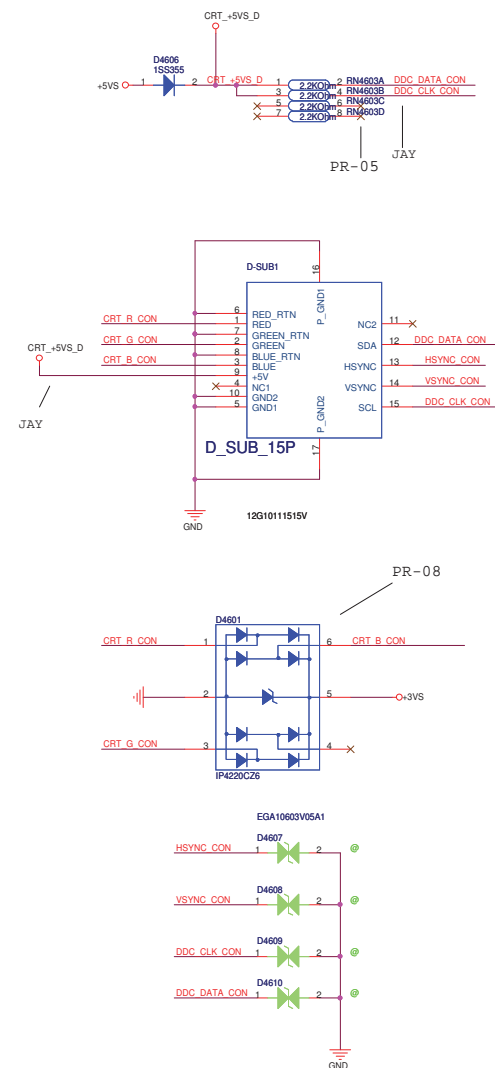
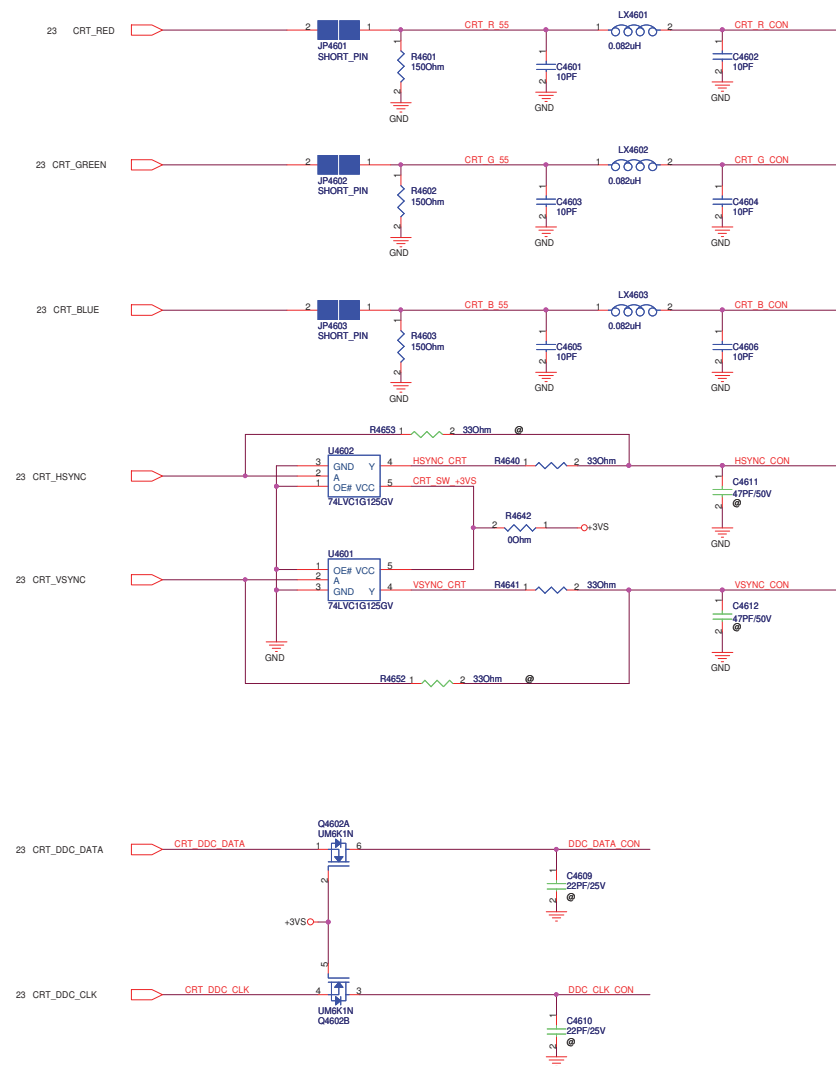
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Size Custom	Project Name K42Jv		Rev 1.3
Date: Thursday, February 11, 2010		Sheet 42 of 99	



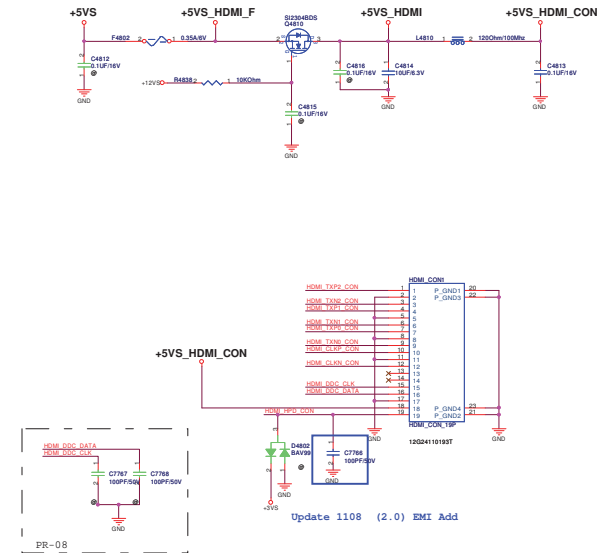
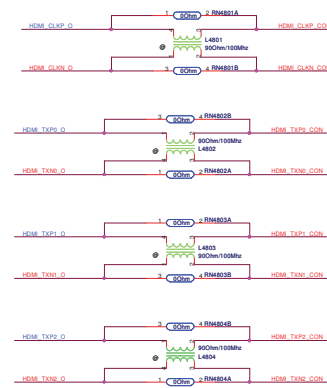
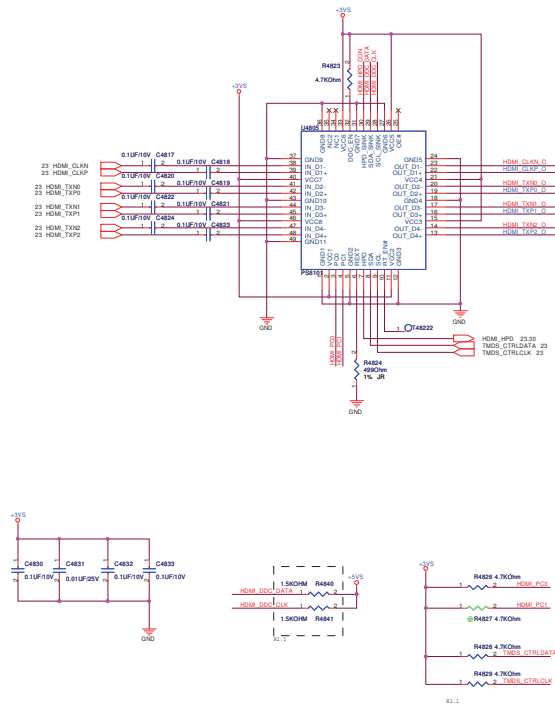
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Size C	Project Name K42Jv		Rev 1.01
Date: Thursday, February 11, 2010		Sheet	43 of 95

LPC Debug Port

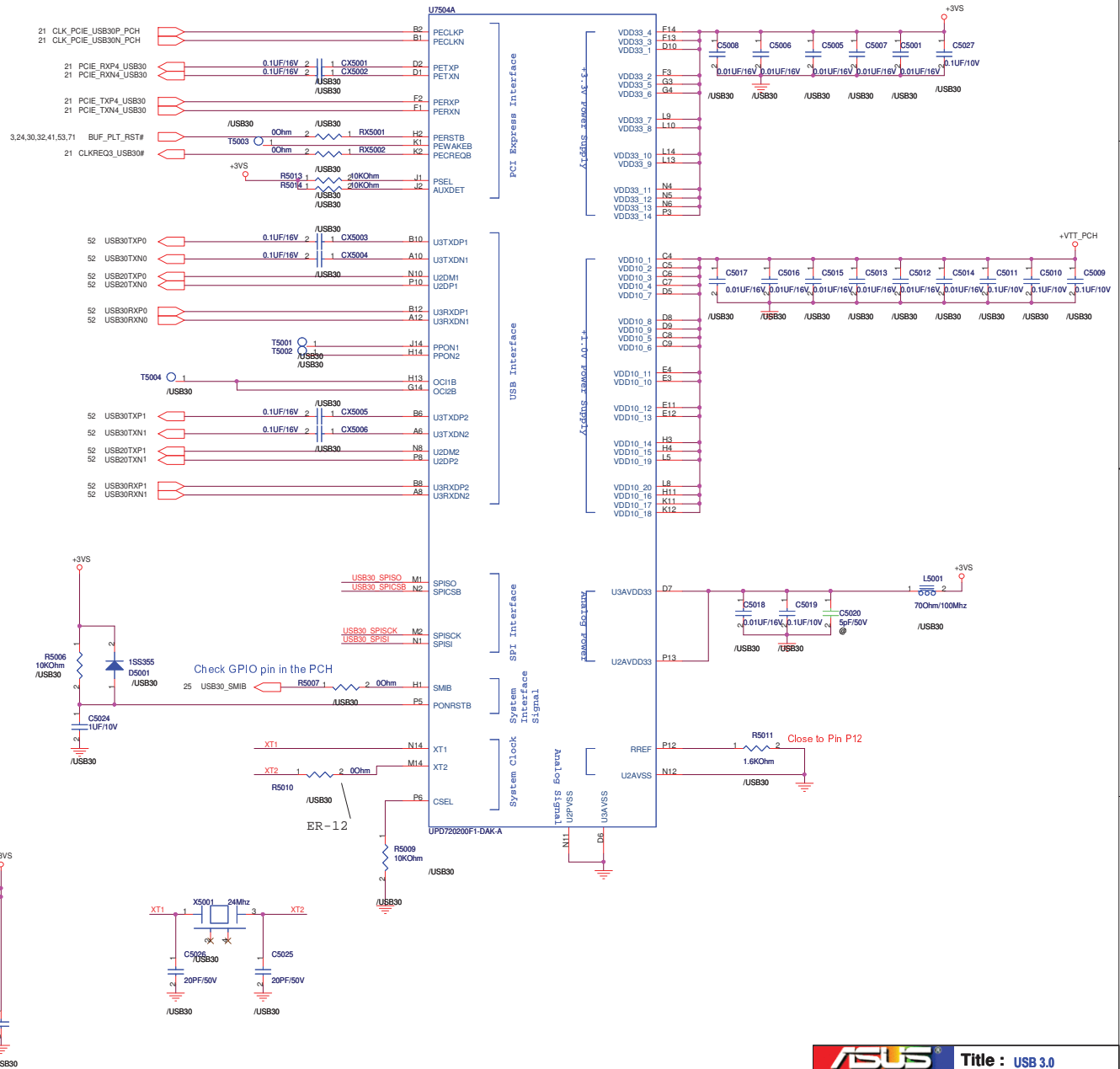
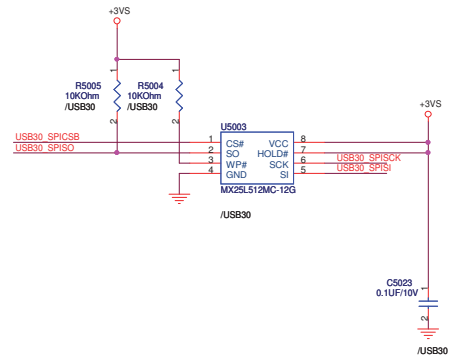
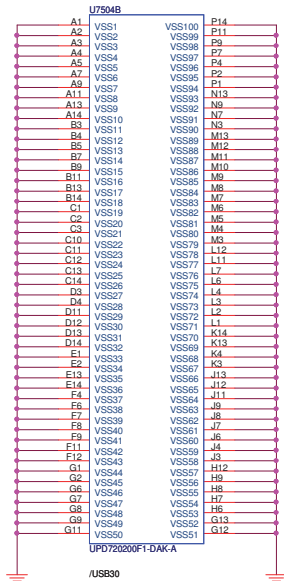




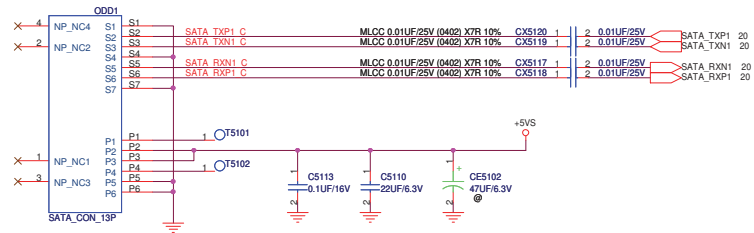




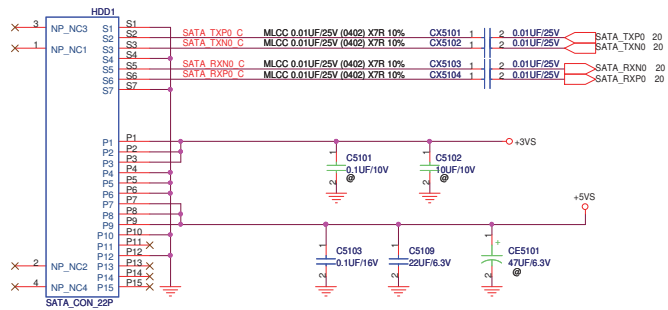
Main Board

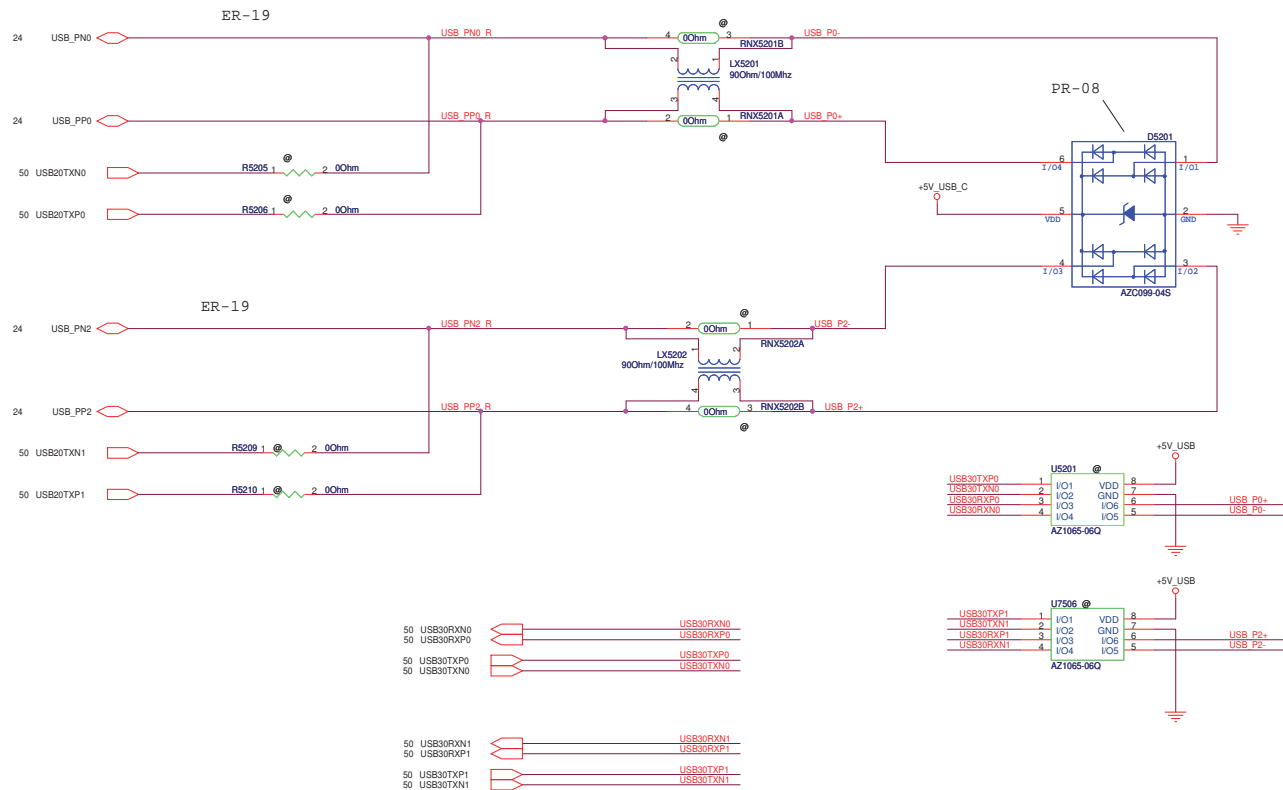
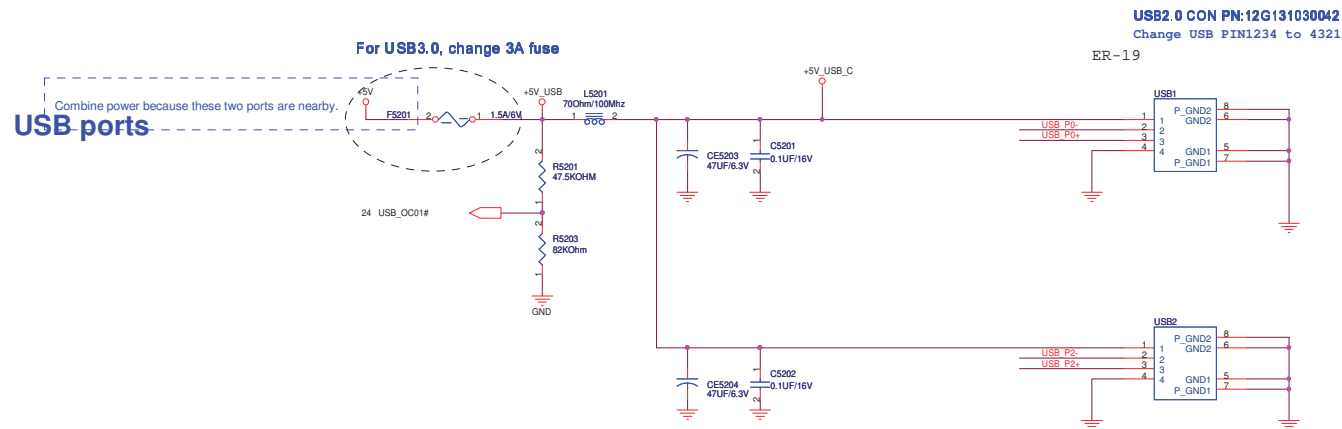


ODD

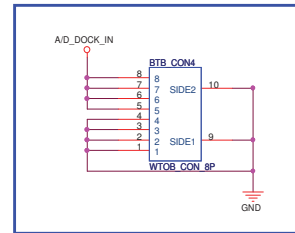


HDD (1st)

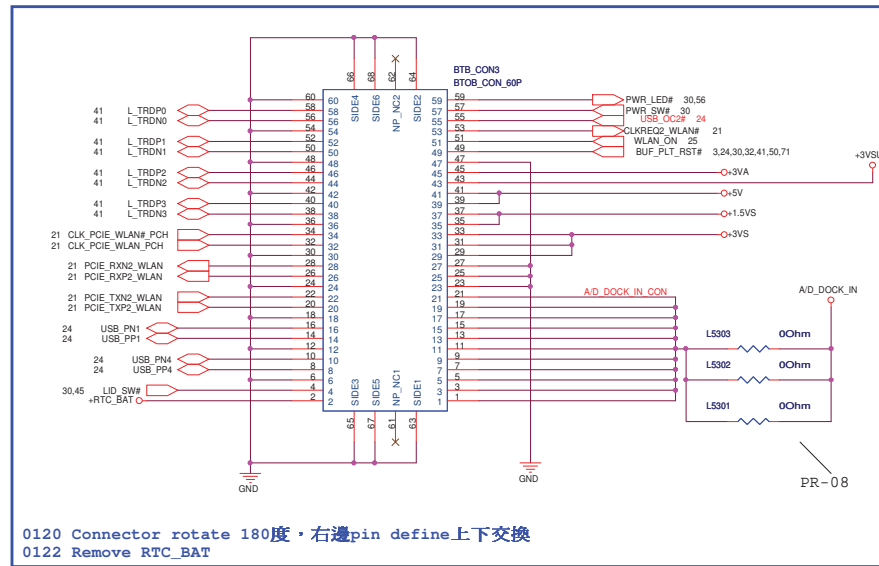




0125 Add 8 pin WtoB connector



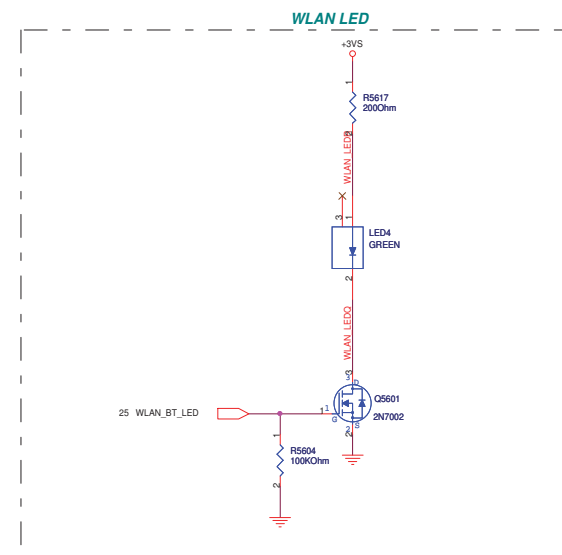
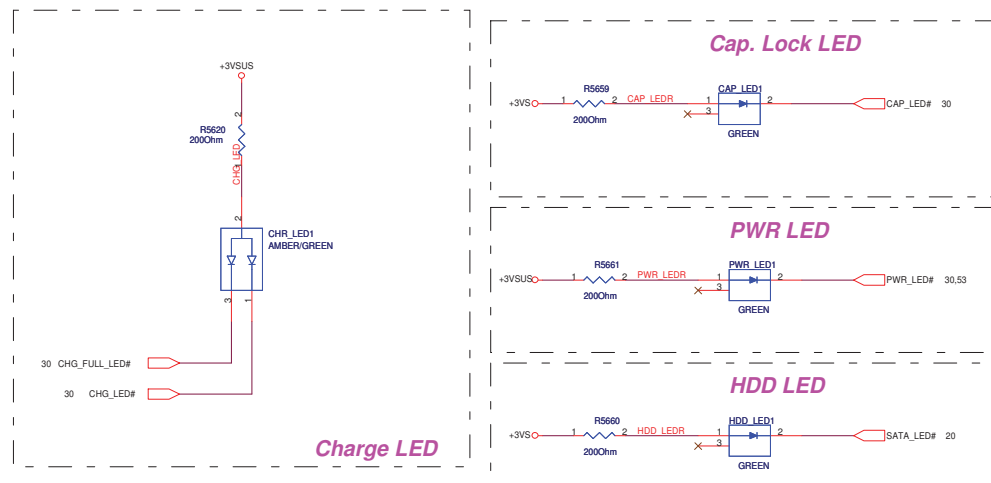
PR-07



PR-08

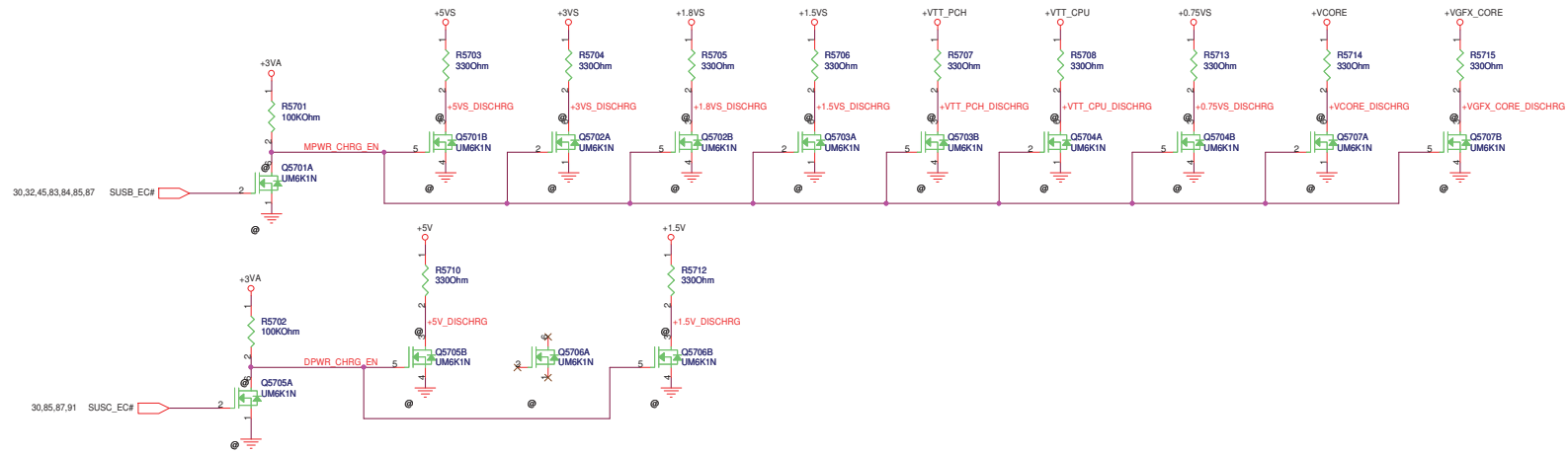
Main Board

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ASUSTeK COMPUTER INC. NB4		Engineer: JAY_TSAI	
Size C	Project Name K42Jv	Rev 1.01	
Date: Thursday, February 11, 2010		Sheet	55 of 95



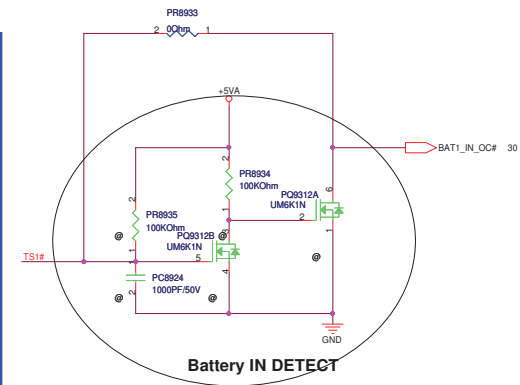
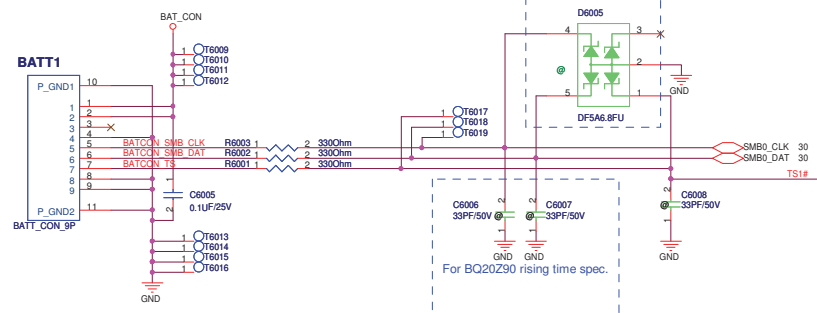
Change LED part number

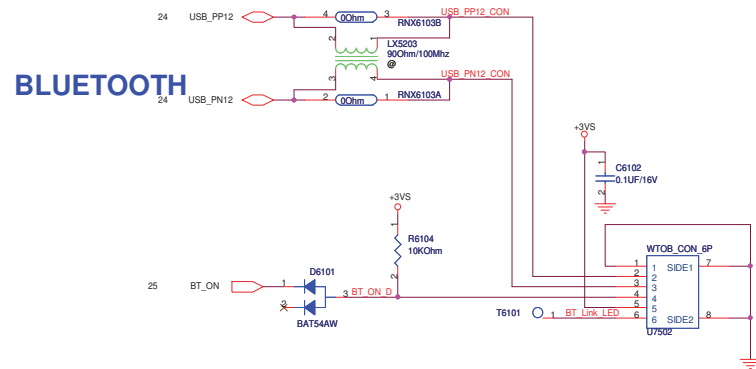
Remove +2.5Vs is for ATI GFX



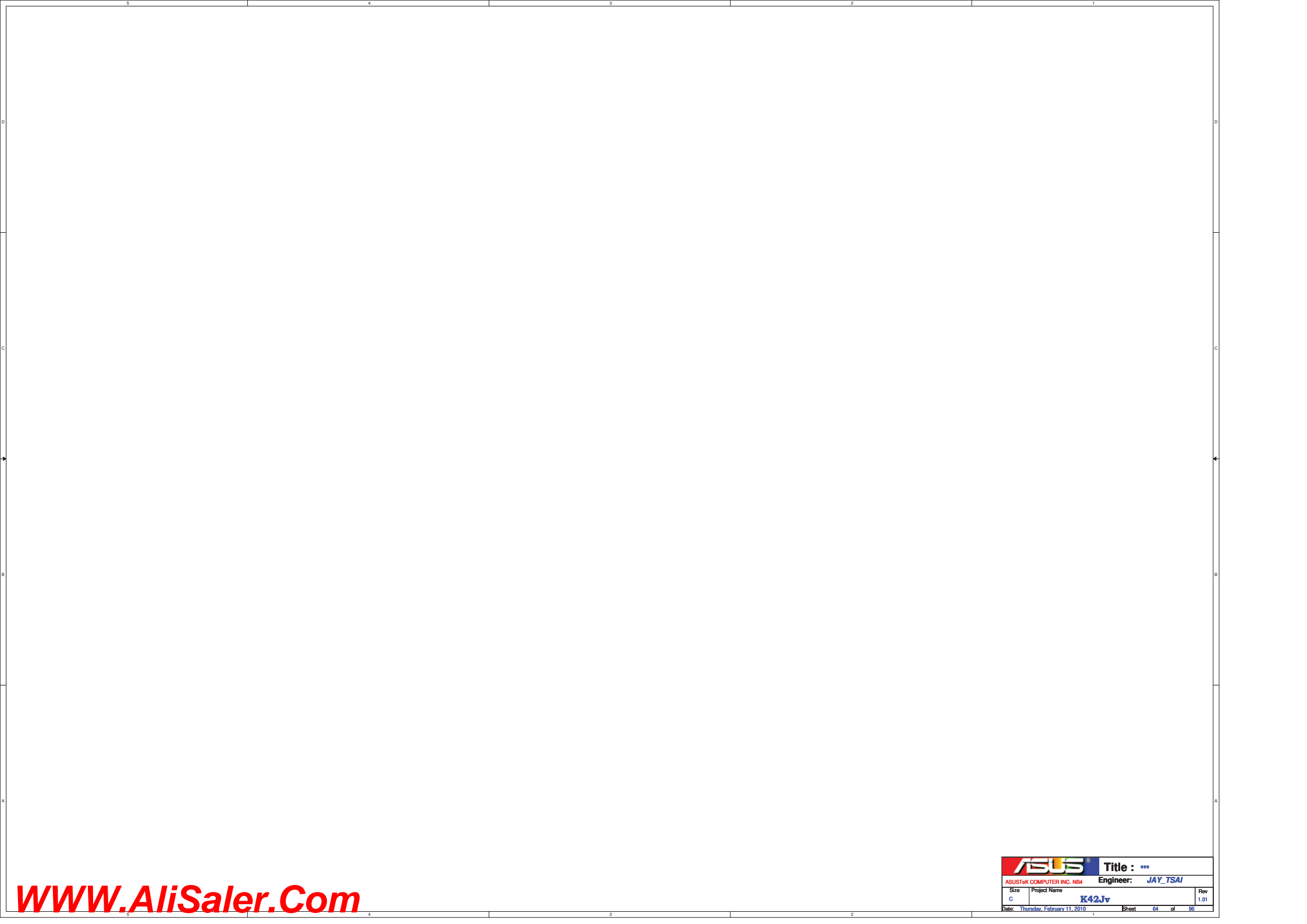
Main Board

Battery Connector



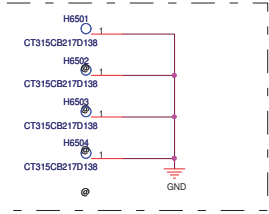


Main Board

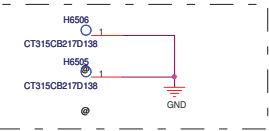


Main Board

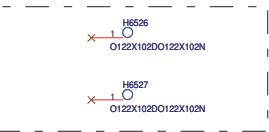
For CPU



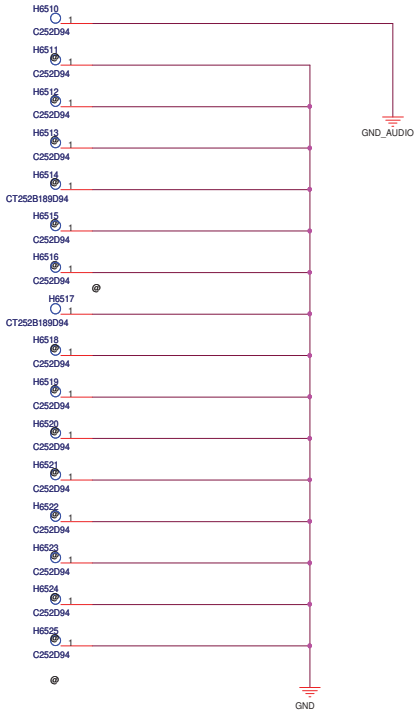
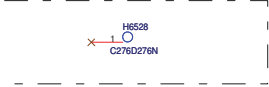
For GPU

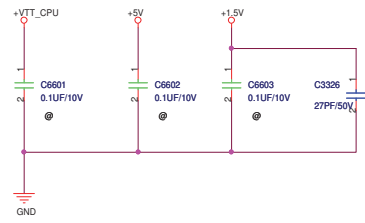


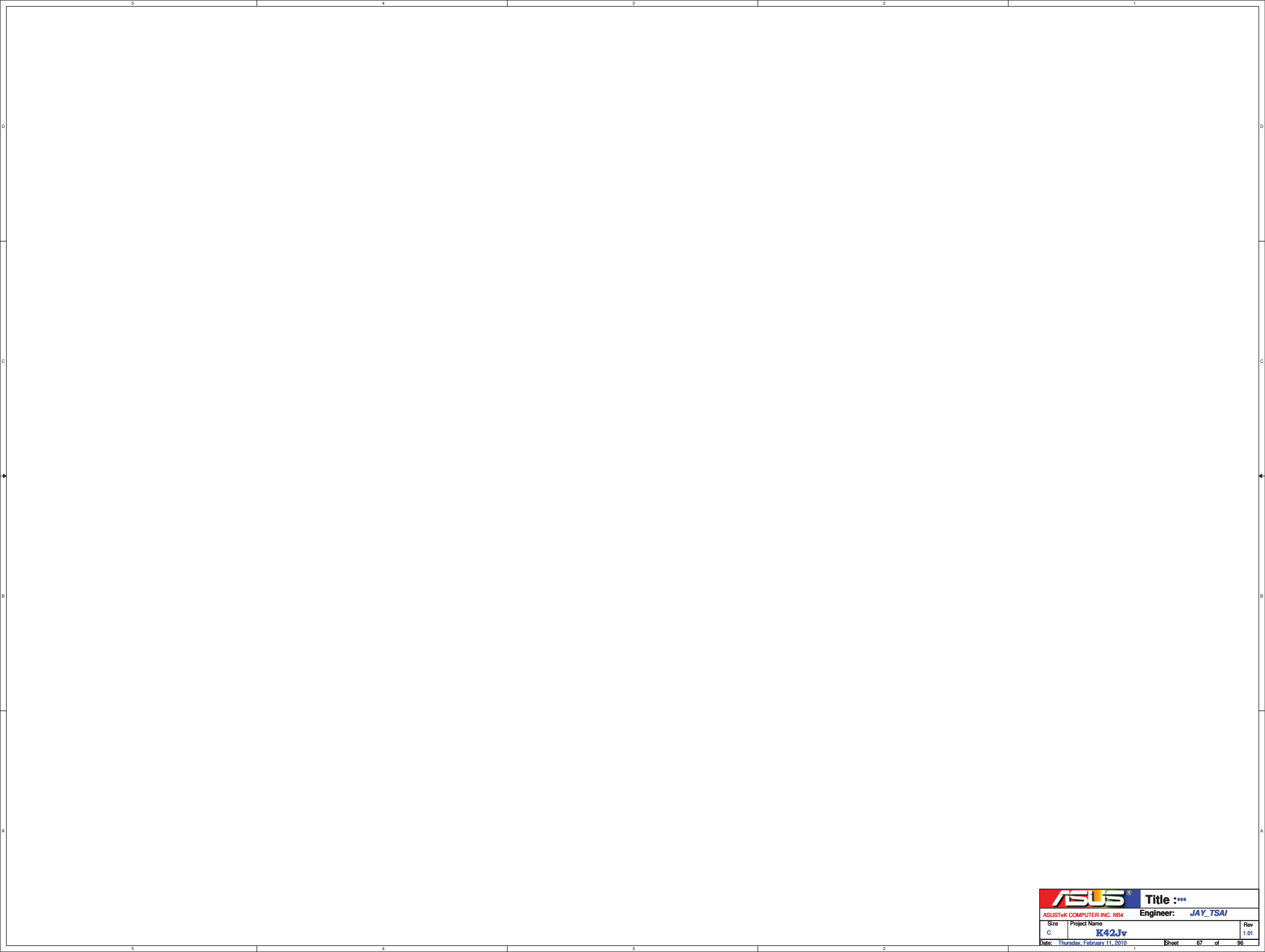
For 橢圓定位孔



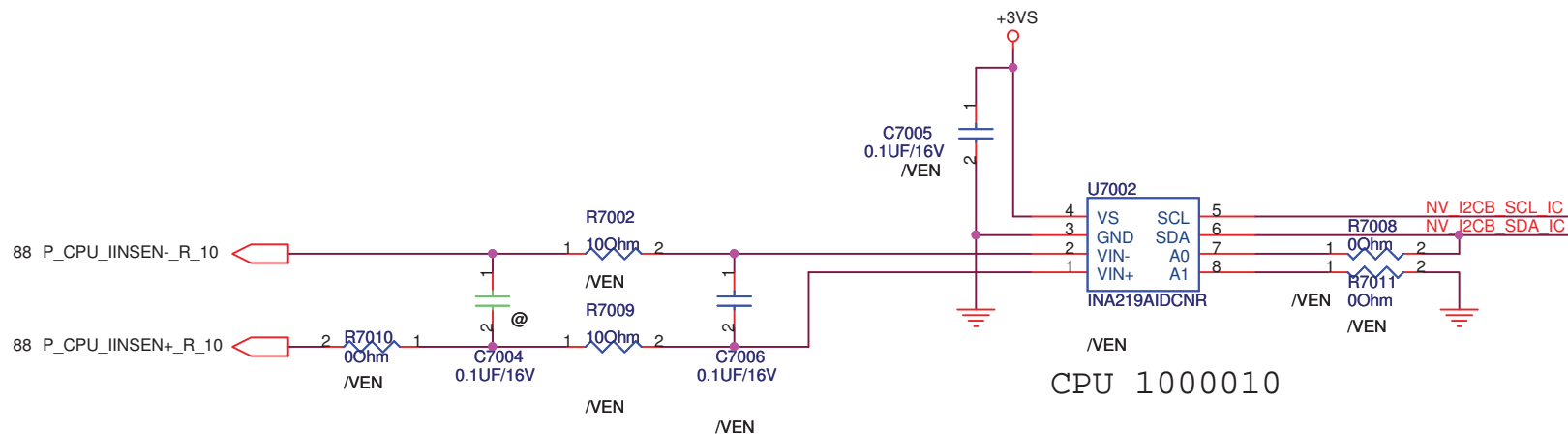
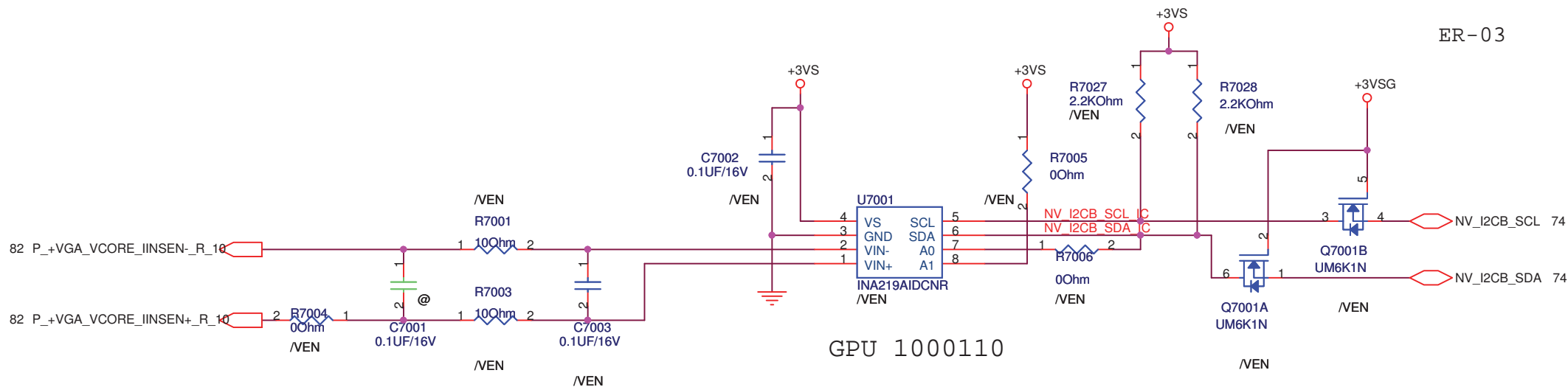
HHD 呼吸孔

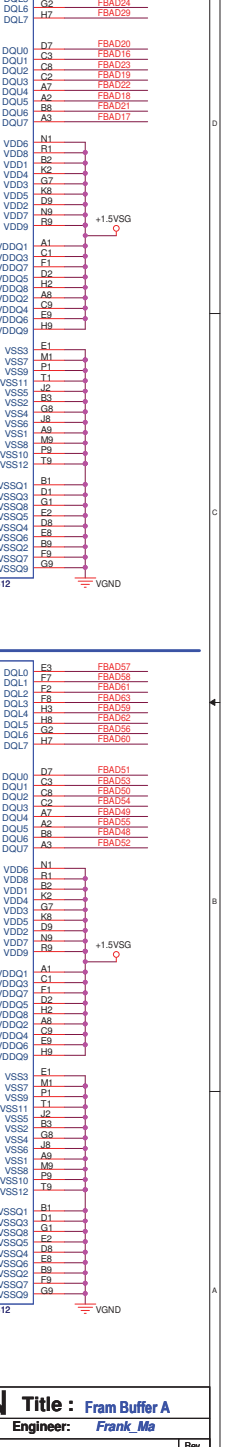
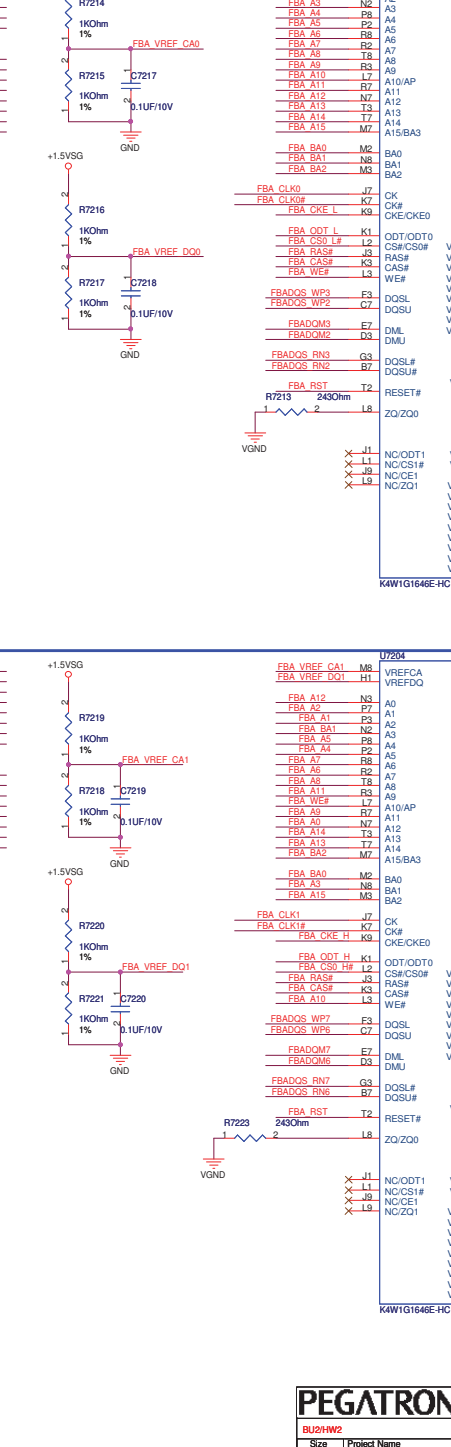
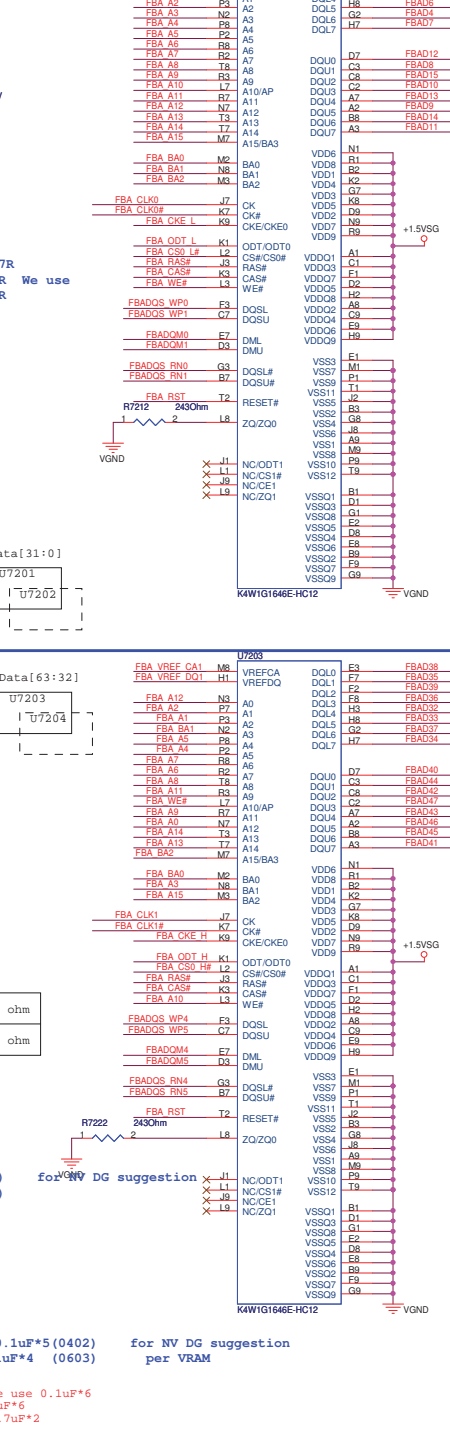
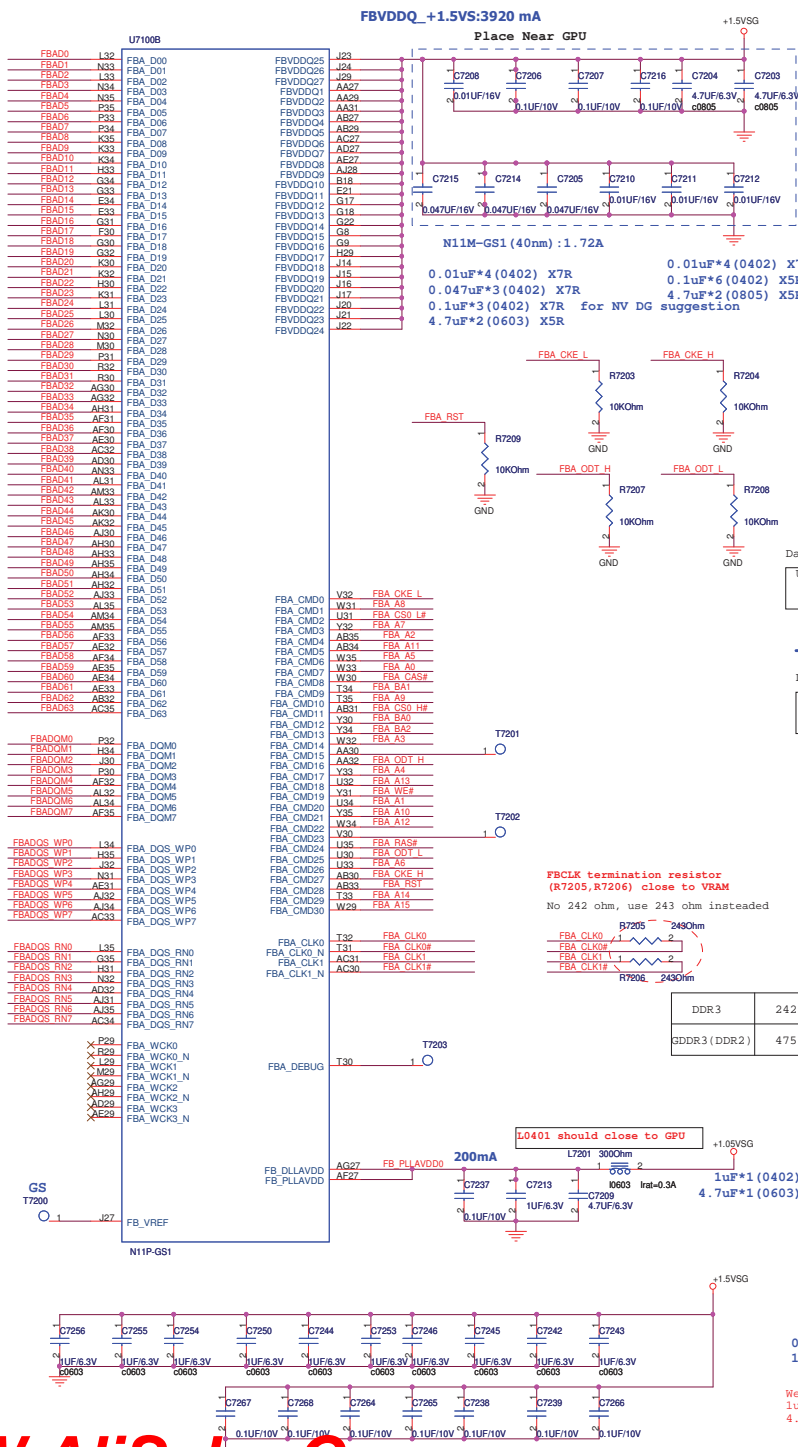


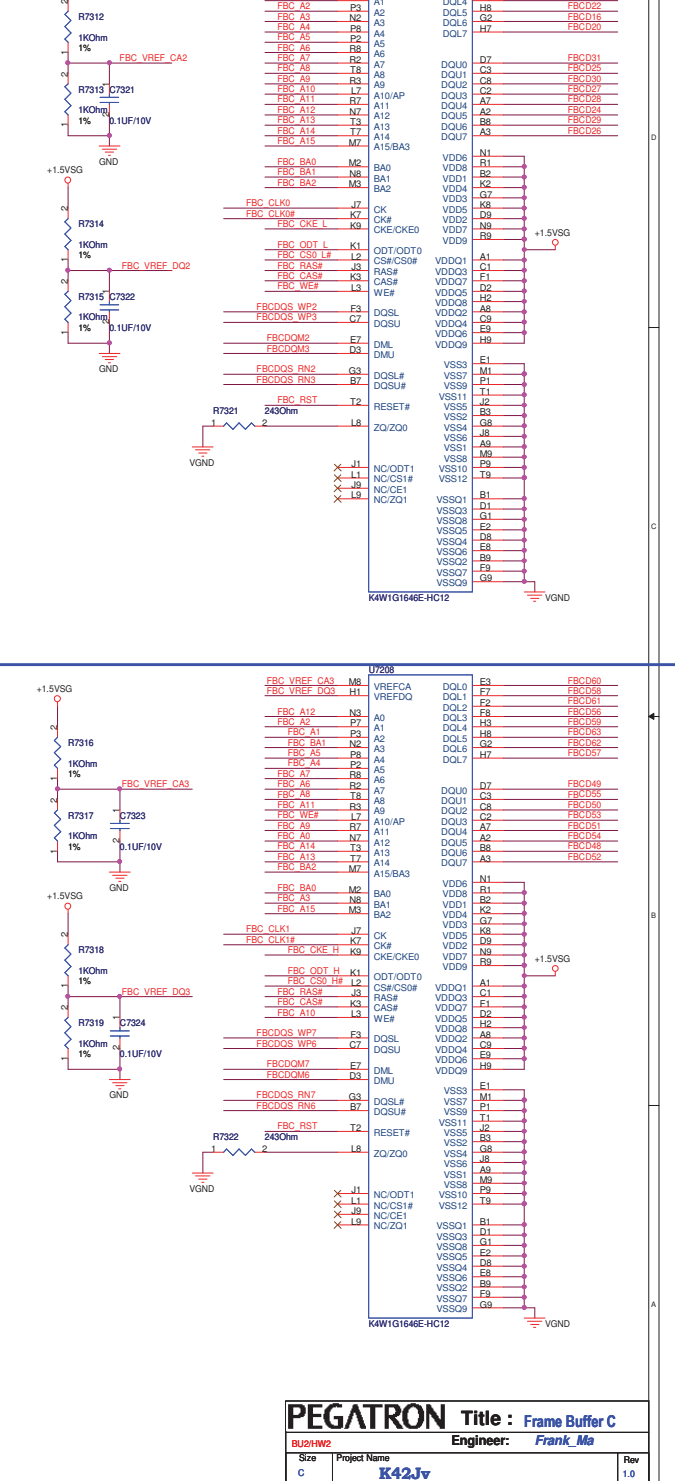
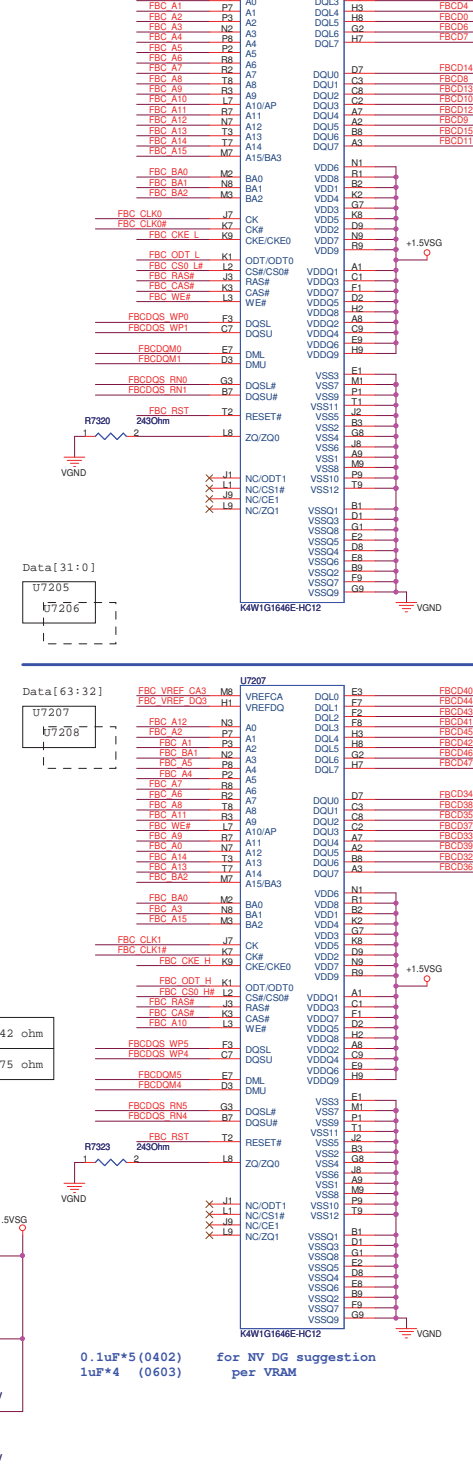




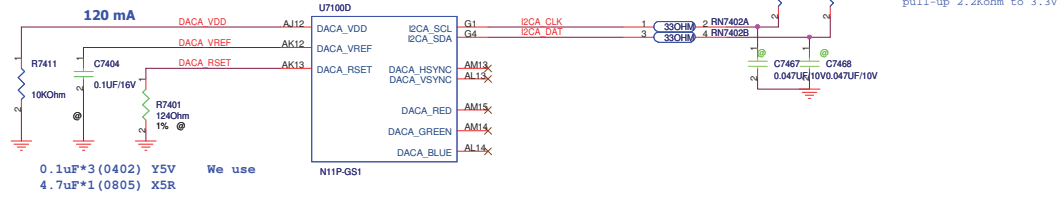




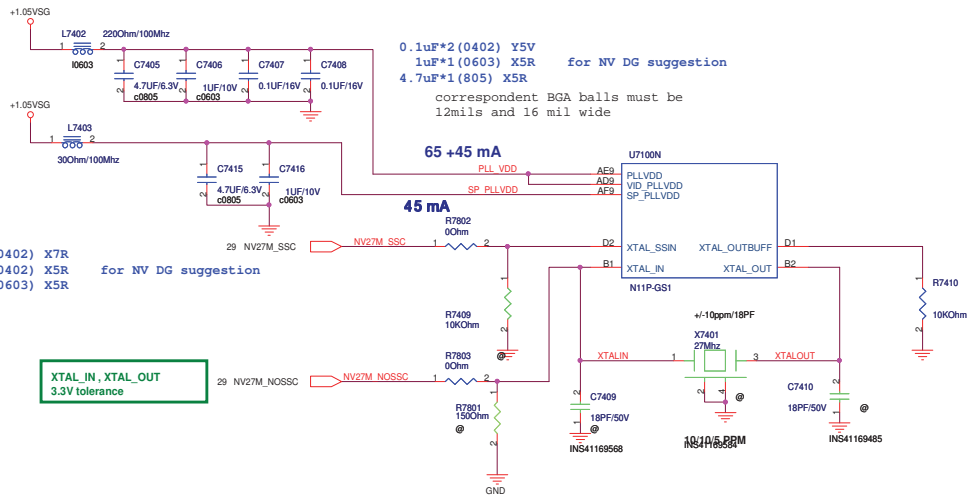
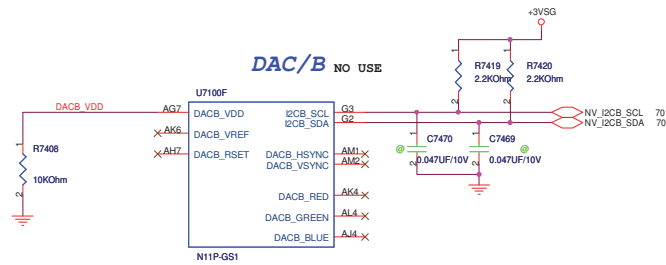




CRT (DAC/A)



DAC/B NO USE

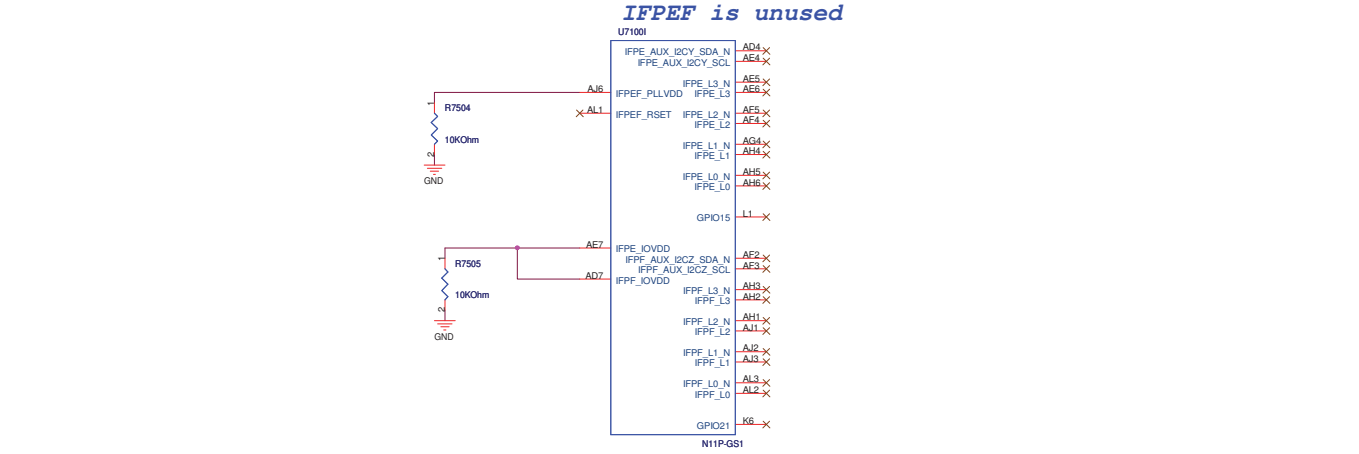
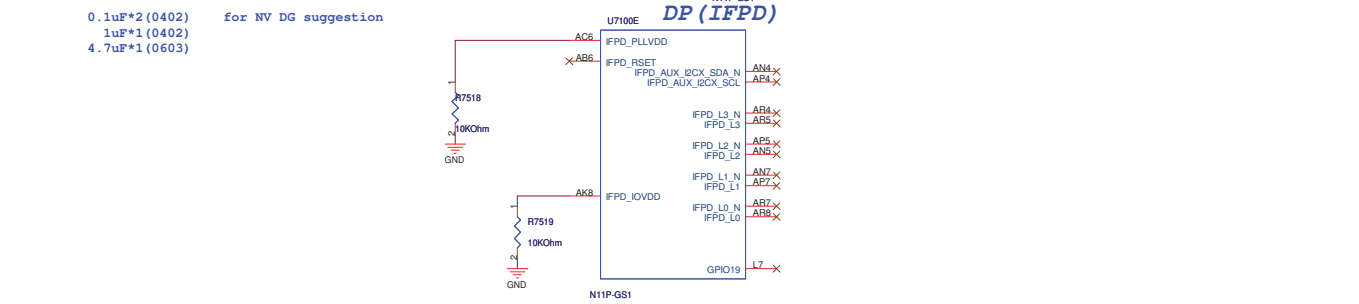
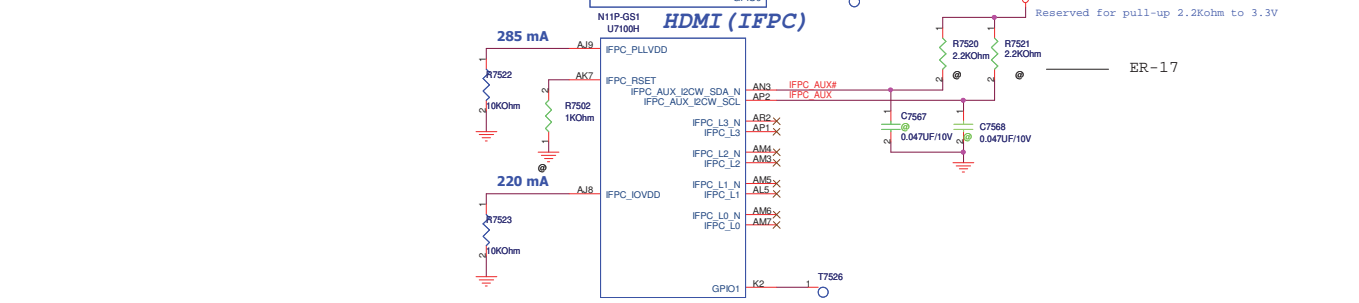
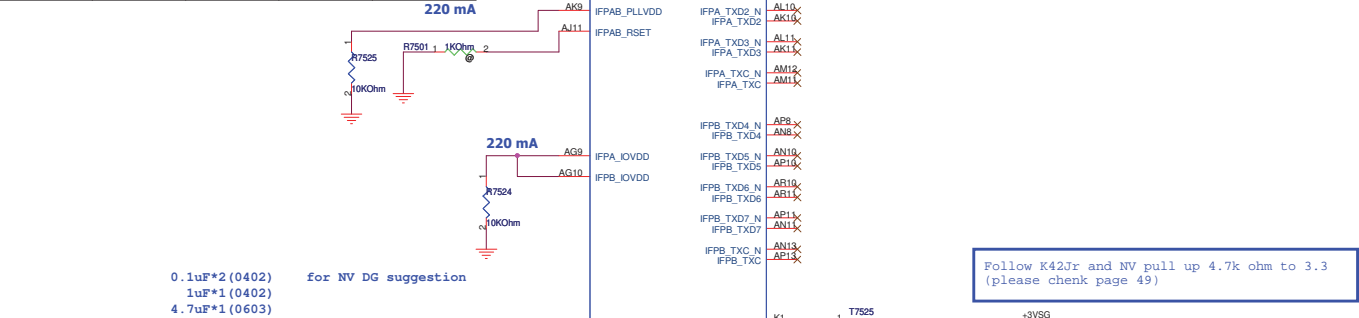


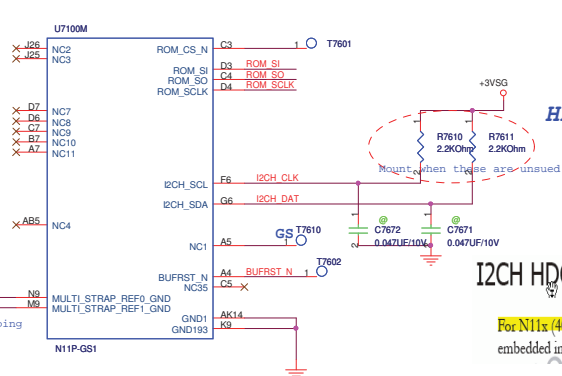
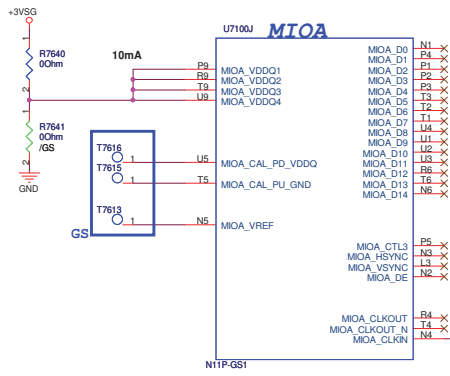
Option /SSC and /XTAL unmount

Ask to FAE if necessary or not

PEGATRON		Title : DACs, CLK GEN	
BU21HW2		Engineer: Frank Ma	
Size	Project Name	Rev	
C	K42Jv	1.0	
Date: Thursday, February 11, 2010		Sheet	74 of 97

GPU	IFP A	IFP B	IFP C	IFP D
GB1-128	LVDS (Single Link)	LVDS (Dual Link)	HDMI	DisplayPort (unused)

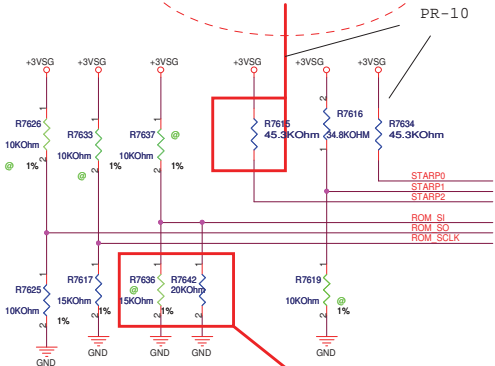




Strap

Check with FAE

Pull up (GPU type) - R7615
N11P-GS1 (40nm) => 45.3K ohm



PR-10
ER-04
Pull down (Memory type)
N11 64*16 DDR3
SAMSUNG => 20K (R7642)
HYNIX => 15K (R7636)

I2CH HDCP Interface

For N11s (40 nm), an external HDCP ROM is not required. HDCP functionality is embedded in the GPU. External connections are not required to support HDCP.

Table 13-5. Multilevel Strapping Options

Physical Strapping Pin	Power Rail	Logical Strapping Bit 3	Logical Strapping Bit 2	Logical Strapping Bit 1	Logical Strapping Bit 0
ROM_SO	VDD33	XCLK_417	FB_0_BAR_SIZE	SMB_ALT_ADDR	VGA_DEVICE
ROM_SCLK	VDD33	PCI_DEVID[4]	SUB_VENDOR	SLOT_CLK_CFG	PEX_PLL_EN_TERM
ROM_SI	VDD33	RAMCFG[3]	RAMCFG[2]	RAMCFG[1]	RAMCFG[0]
STRAP2	VDD33	PCI_DEVID[3]	PCI_DEVID[2]	PCI_DEVID[1]	PCI_DEVID[0]
STRAP1	VDD33	3GIO_PADCFG[3]	3GIO_PADCFG[2]	3GIO_PADCFG[1]	3GIO_PADCFG[0]
STRAP0	VDD33	USER[3]	USER[2]	USER[1]	USER[0]

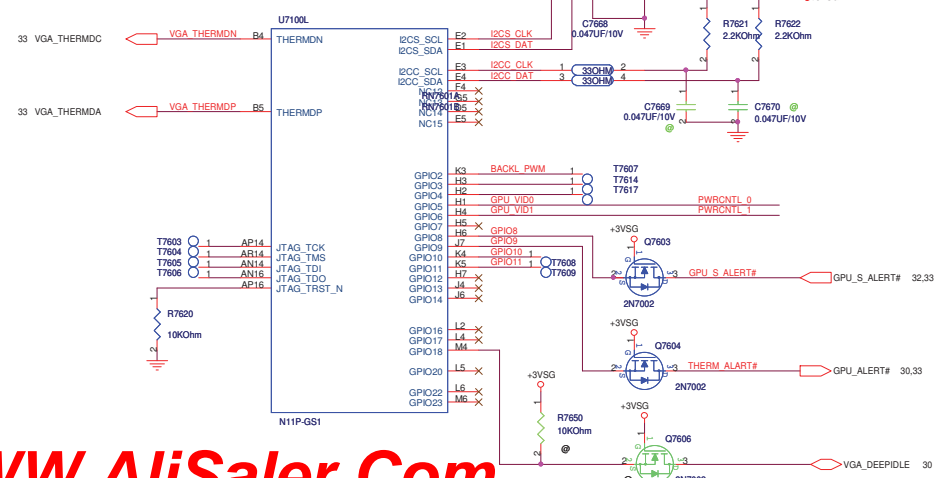
I2C ASSIGNMENTS

I2CA: CRT --3V
I2CB: N/A
I2CC: LVDS (EDID)
I2CS: Slave for GPU internal thermal
I2CH: HDCP
IFPC_AUX_I2CW: HDMI --3 V
IFPD_AUX_I2CX: DP --3 V
IFPE_AUX_I2CY: N/A
IFPF_AUX_I2CZ: N/A

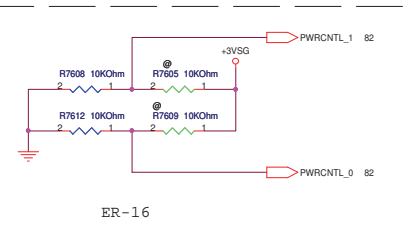
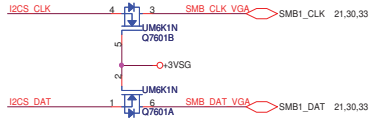
GPIO ASSIGNMENTS

GPIO	I/O	ACTIVE	USAGE
0	n/a	n/a	p.75
1	IN	-	IFPC HPD-C (HDMI) p.75
2	OUT	HIGH	PANEL BACKLIGHT PWM
3	OUT	HIGH	PANEL POWER SNABLE
4	OUT	HIGH	PANEL BACKLIGHT ENABLE
5	OUT	-	NVVD VID 0
6	OUT	-	NVVD VID 1
7	OUT	-	NVVD VID 2
8	I/O	LOW	OVER THERMAL ALERT
9	I/O	LOW	Memory VREF switch
10	OUT	-	SLI raster sync
11	I/O	LOW	AC DETECT
12	IN	-	IFPE HPD-E
13	OUT	-	FAN PWM
14	OUT	-	Reserved
15	IN	-	Reserved
16	IN	-	IFPD HPD-D (DP) p.75
17	IN	-	Reserved
18	IN	-	IFPF HPD-F
19	IN	-	SLI swap ready signal
20	IN	-	
21	IN	-	
22	IN	-	
23	I/O	-	

GPIO



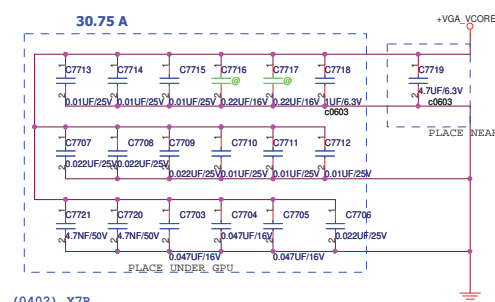
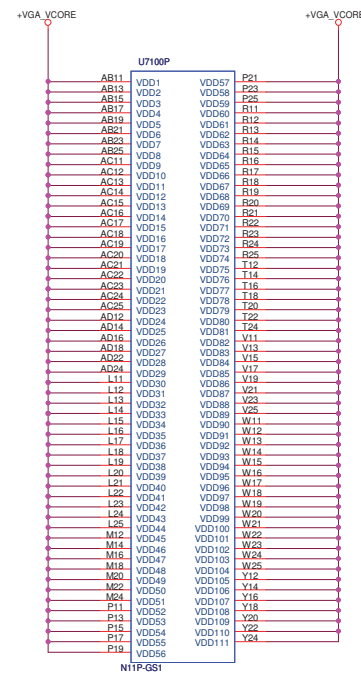
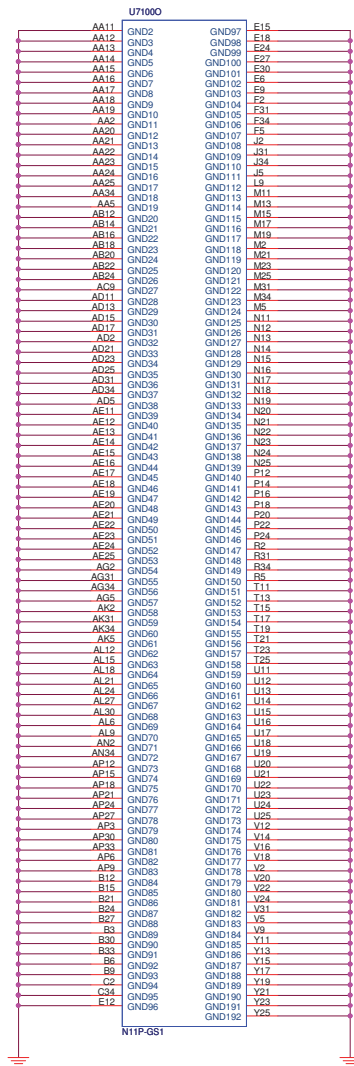
Use internal thermal diode



ER-16

PEGATRON Title : Strap, GPIO

BU2HW2	Project Name	Engineer: Frank Ma
Size C	K42Jv	Rev 1.0
Date: Thursday, February 11, 2010	Sheet 76 of 97	



4700pF*2 (0402) X7R
 0.01uF*6 (0402) X7R
 0.022uF*4 (0402) X7R
 0.047uF*3 (0402) X7R
 0.22uF*2 (0603) X7R
 1uF*1 (0603) X5R
 4.7uF*1 (0603) X5R

for NV DG suggestion

0.1uF*15 (0402) X5R
 0.22uF*2 (0603) X7R @
 1uF*1 (0603) X5R
 4.7uF*1 (0603) X5R

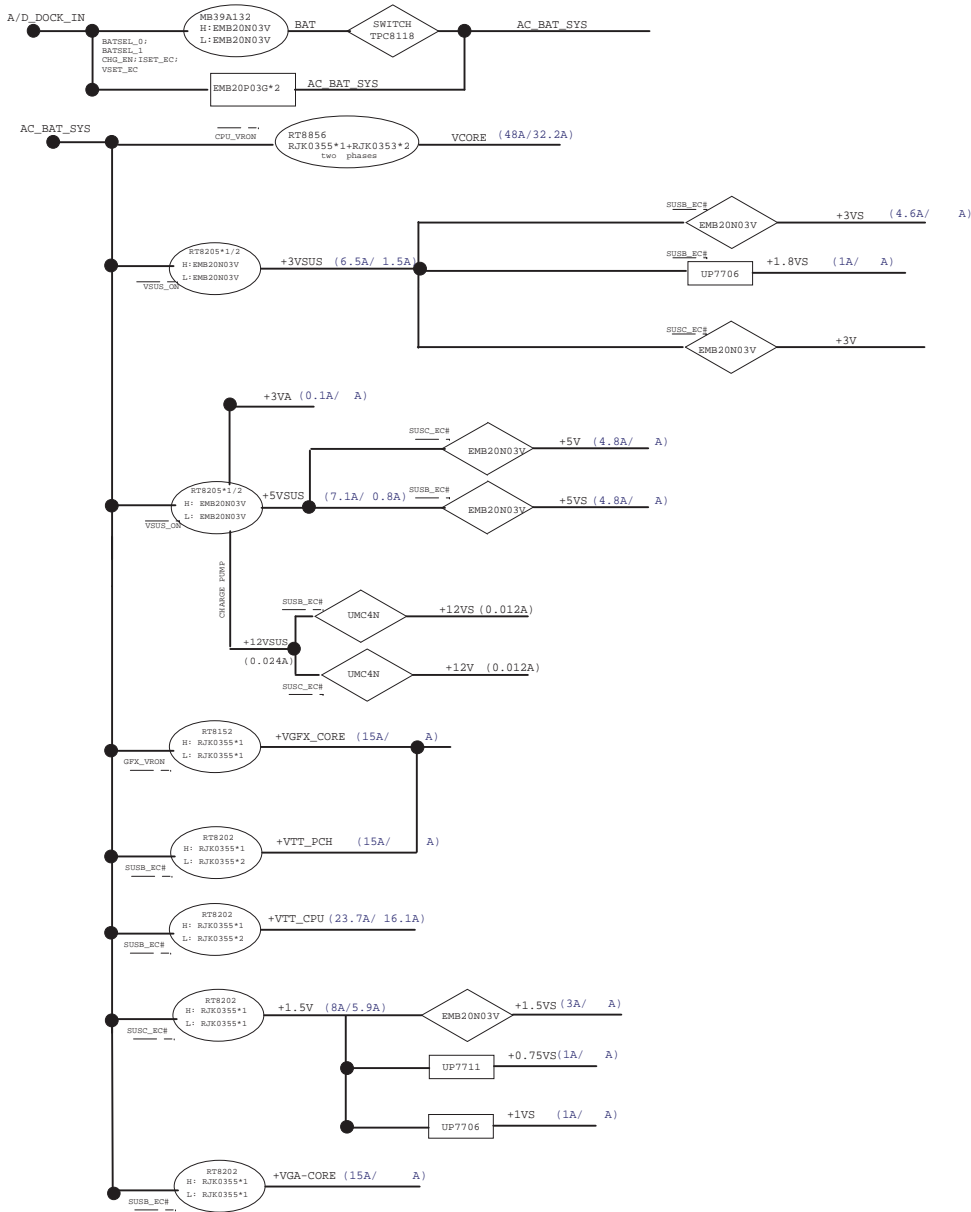
We use

ER Modify list:

- ER-01 : For VTT Power adjustable and DRAM power fix
 - ER-02 : Exchange PIN 2 and PIN 3 connection and Power rail chagne from +3VS to +5VS.
 - ER-03 : Add /Ven lable for Ventura option.
 - ER-04 : According GPU strap define setting to P.D.
 - ER-05 : LCD backlight control change to accord DESIGN IP.
 - ER-06 : Change R2404 to 330HM for EA measurement.
 - ER-07 : Unmount External thermal sensor change to use DGPU internal thermal sensor.
 - ER-08 : According for VTT power default setting.
 - ER-09 : To change from +1.8VSG to +1.5VSG.
 - ER-10 : PCB ID change from SR to ER setting.
 - ER-11 : ALC269 ver B. must add 10K P.U for PD# pin.
 - ER-12 : Modify Crystal Rd location and add /USB30 lable.
 - ER-13 : For Smart33 Down freq. and reserve over clock design.
R2933 mount 4.7K 0603 at ER stage.
 - ER-14 : Modify power rail to +5VS_AUDIO.
 - ER-15 : R3631 change from 10K to 0R.
 - ER-16 : Setting DGPU Vcore default power to 0.8V.
 - ER-17 : Unmount R7520,R7521 from vendor suggestion.
 - ER-18 : Reserve vendor solution add 0R for bypass other circuit.
 - ER-19 : Change USB port to 2.0 connector and design only for USB 2.0.
 - ER-20 : For line-in channel ,HP jack sensor must change to 10K.
 - ER-22 : To resolve "3622146 A Voltage Spike on Graphics Core Rail (Vaxg) to 1.5V seen during system shutdown"change from 4.7K to 470 OHM.
 - ER-23 : Follow Design IP,change to P.D.
 - ER-24 : Change mount for smart 33 control Vcore power.
- For cost down and short jump ,Please search "C.D"

PR Modify list:

- PR-01 : Change R2933 to 10K 0402.
- PR-02 : Mic bias voltage change from +5VS_AUDIO to CODEC's PIN28(integreated regulator).To avoid MIC noise by drity power.
- PR-03 : Change R3631 from 0R to short jump.
- PR-04 : Add level shift circuit.
- PR-05 : Del RN9250.
- PR-06 : Add for pop and click sounds.
- PR-07 : Change for B to B re-design.(copy from K42JC schematic)
- PR-08 : EMI/ESD request.
- PR-09 : Add MGRL of headset device design.
- PR-10 : According to vendor suggestion.(45K change to 45.3K)
- PR-11 : Bypass INT. MIC amplifier.
- PR-12 : VTT,+1.5V,VCORE power set to default normal power rails.
- PR-13 : Codec IC(ALC269) change from VB2 to VB5.
- PR-14 : PCB ID change from ER to PR setting.



PWRCNTL_1	PWRCNTL_0	VGA_VCORE
0	0	0.801V
0	1	0.852V
1	0	0.901V
1	1	0.952V

Controller

1. Voltage & Current:
+1.2VSUS: 16A

2. Frequency:
Ton=3.85p*Rt(on)/Vin-05=0.3us
Frequency=Vout/(Vin*Ton)=500KHZ

Set PR8107=21.5kohm
Iocp=Rocp*20/Rds(on)=26A

4. Soft start time:
Soft-Star duration is 1.35ms

5. Inrush Current:
C total =220uF
I inrush=0.163A

Power stage

1. I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 0.85A$

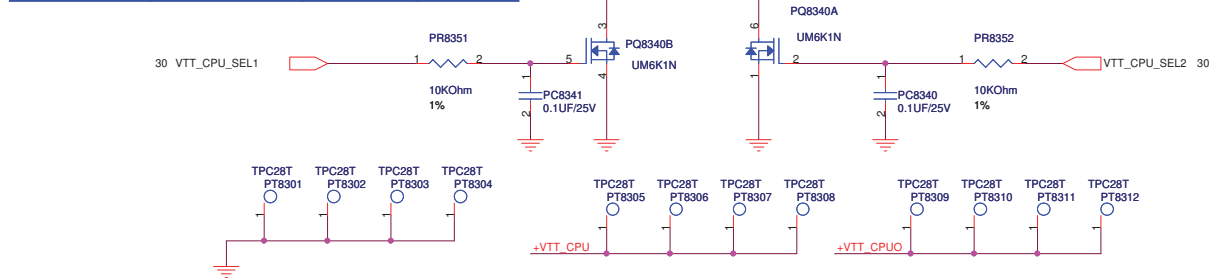
2. Ripple Current:
Ripple=3.74A

3.ripple voltage:
 $I_{peak} = (v_{in} - v_o) \cdot D / (L \cdot F_{sw}) = 2.07A$
DCR=3.3mohm
V=6.831mV

4. Inductor Spec: 3. OCP:
Isat=25A
Idc=15.5A
DCR=5.5mohm

5. MOSFET Spec:
H-side and L-side MOSFET:
Rds(on)=16.5mOhm (Vgs=4.5V)
Icont=30A (T=25)
Ipeak=120A (Pause<10us)

VTT_CPU_SEL1	VTT_CPU_SEL2	+VTT_CPU	
0	0	1.041V	DV3
0	1	1.059V	DV2
1	0	1.078V	DV1
1	1	1.097V	Normal



Controller

- Voltage & Current:**
+VCCP: 1.05V@10A
- Frequency:**
Ton=3.85p*Rt(on)/Vin-05=0.3us
Frequency=Vout/(Vin*Ton)=500KHZ
- OCP:**
Set PR7343=18KOhm
Iocp=Rocp*Rds(on)=22A
- Soft start time:**
Soft-Star duration is 1.35ms
- Inrush Current:**
C total = 200 uF
I inrush= 0.16 A

Power stage

- I/P Current:**
I in = Vo*Io/(0.75 * Vin) = 2.3 A
- Ripple Current:**
Iripple=2.8A
- Dynamic:**
Ipeak=1.98A
DCR=3.3mohm
V=6.534mV
- Inductor Spec:**
Isat=16A
Idc=11A
DCR=9mOhm
- MOSFET Spec:**
H-side and L-side MOSFET: RJK0355DPA-00-JO WPAK
Rds(on)=16.5mOhm (Vgs=4.5V)
Icont=30A (T=25)
Ipeak=120A (Pause<10us)

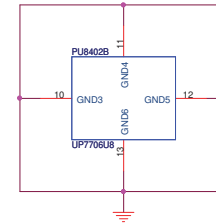
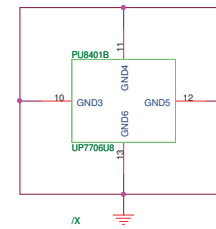
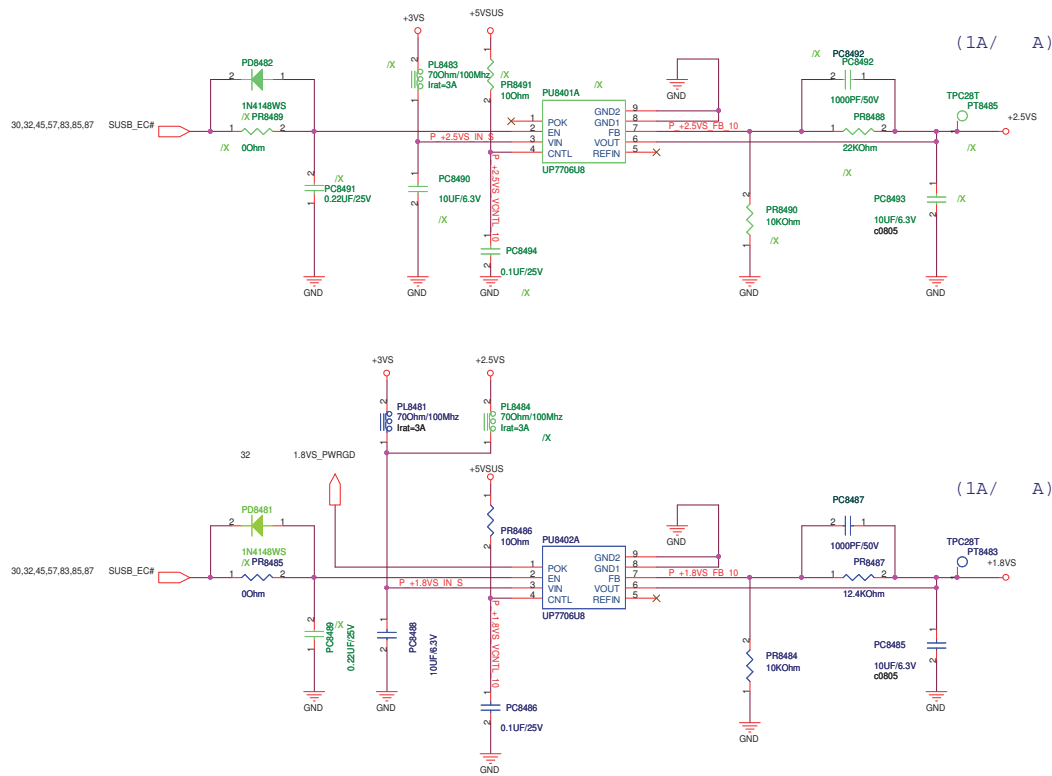
Variant Name:

ASUS Title : Power_+VCCP

ASUSTeK COMPUTER INC Engineer:

Size	Project Name	Rev
Custom		1.0

Date: Thursday, February 11, 2010 Sheet 83 of 1



Controller		Power stage	
1. Voltage & Current: +1.8V: +1.8V & 12A		1. I/P Current: $I_{in} = V_o \cdot I_o / (0.8 \cdot V_{in}) = 0.947A$	
2. Frequency: $T_{on} = 3.85p \cdot R_t(ON) \cdot V_o / V_{in} - 0.5$ $Frequency = V_{out} / (V_{in} \cdot T_{on}) = 500KHZ$		2. Ripple Current: $I_{ripple} = 2.342A$	
3. OCP: $Set PR7343 = 18kohm$ $I_{ocp} = R_{ocp} \cdot 20 / R_{ds(ON)} = 20 \cdot 21.5 / 18.5 = 26A$		3. Ripple Voltage: $I_{peak} = (V_{in} - V_o) \cdot D / (L \cdot F_{sw}) = 3.25A$ $DCR = 3.3mohm$ $V = 10.75mV$	
4. Soft start time: Soft-Star duration is 1.35ms		4. Inductor Spec: $I_{sat} = 36A$ $I_{dc} = 18A$ $DCR = 3.3mohm$	
5. Inrush Current: $C_{total} = 100uF$ $I_{inrush} = 0.133A$		5. MOSFET Spec: H-side and L-side MOSFET: $R_{ds(ON)} = 16.5mOhm$ ($V_{gs} = 4.5V$) $I_{cont} = 30A$ ($T = 25$) $I_{peak} = 120A$ ($Pause < 10us$)	
ASUS		ASUS	
ASUSTek COMPUTER INC		ASUSTek COMPUTER INC	
Project Name		Project Name	
Size		Size	
Date		Date	
Thursday, February 11, 2010		Thursday, February 11, 2010	
Sheet		Sheet	
84		84	
of		of	
1		1	
Rev		Rev	
1.0		1.0	

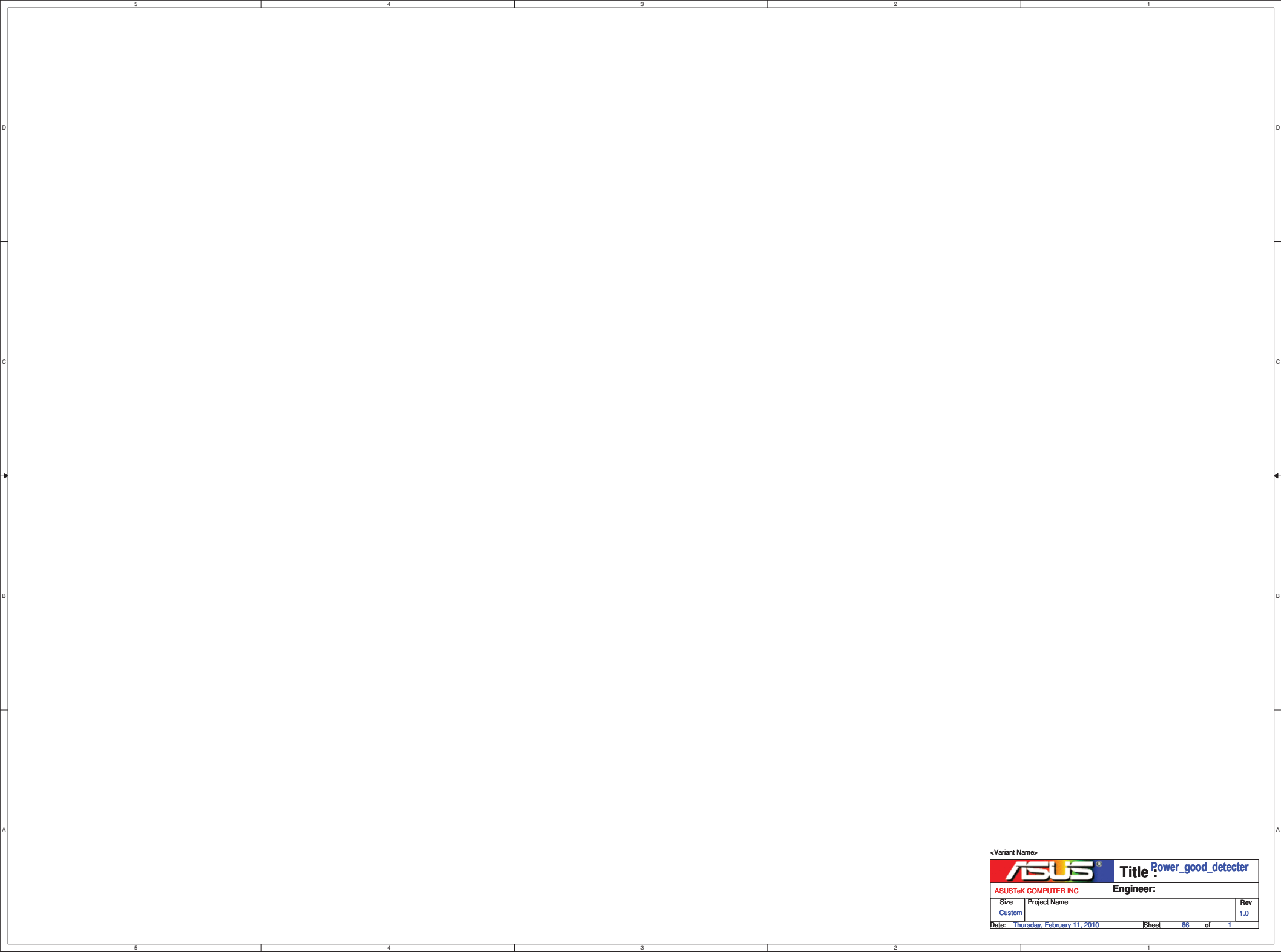
20100204




Engineer:

Date: Thursday, February 11, 2010 Sheet 85 of 1

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<Variant Name>



Title :
Power_good_detector

Engineer:

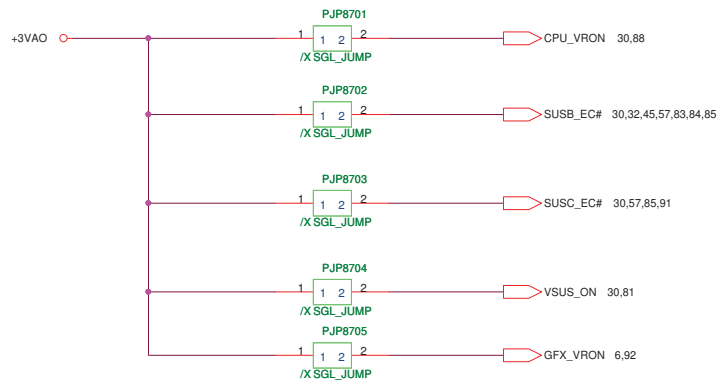
Size
Custom

Project Name


Rev
1.0

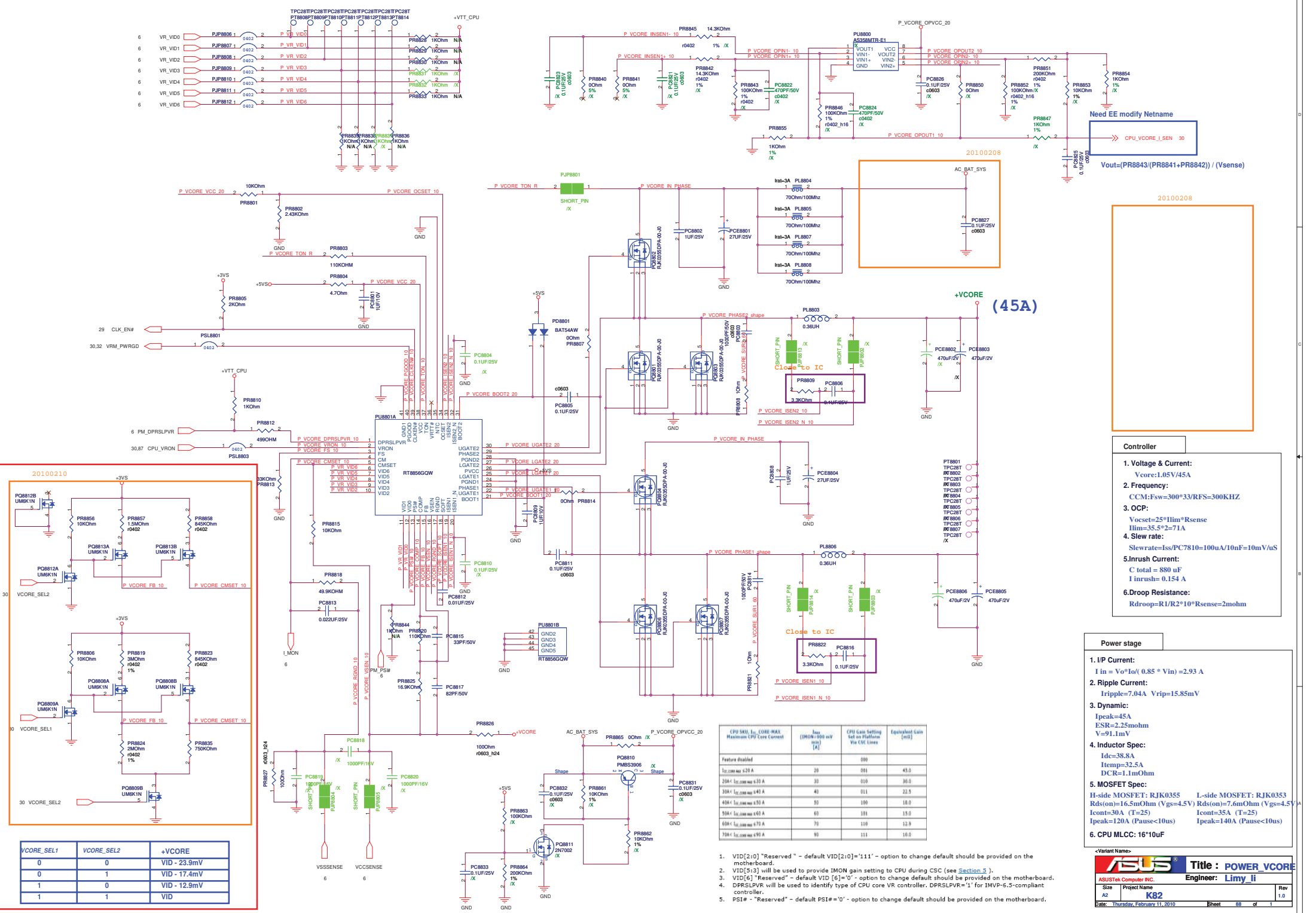
Date: Thursday, February 11, 2010

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<Variant Name>

		Title :Power_for_test	
ASUSTeK COMPUTER INC		Engineer:	
Size	Project Name		Rev
Custom			1.0
Date: Thursday, February 11, 2010		Sheet	87 of 1



Need EE modify Netname
Vout=(PR8843+(PR8841+PR8842)) / (Vsense)

- Controller**
- Voltage & Current:**
Vcore:1.05V/45A
 - Frequency:**
CCM:Fsw=300*33/RFS=300KHZ
 - OCP:**
Vocset=25*Ilm*Rsense
Ilm=35.5*2=71A
 - Slew rate:**
Slewrate=Iss/PC7810=100uA/10nF=10mV/uS
 - Inrush Current:**
C total = 880 uF
1 inrush= 0.154 A
 - Droop Resistance:**
Rdroop=R1/R2*10*Rrsense=2mohm

- Power stage**
- I/P Current:**
 $I_{in} = V_o \cdot I_o / (0.85 \cdot V_{in}) = 2.93 \text{ A}$
 - Ripple Current:**
Iripple=7.04A Vrip=15.85mV
 - Dynamic:**
Ipeak=45A
ESR=2.25mohm
V=91.1mV
 - Inductor Spec:**
Idc=38.8A
Itemp=32.5A
DCR=1.1mOhm
 - MOSFET Spec:**
H-side MOSFET: RJK0353 L-side MOSFET: RJK0353
Rds(on)=16.5mOhm (Vgs=4.5V) Rds(on)=7.6mOhm (Vgs=4.5V)
Icmt=30A (T=25) Icmt=35A (T=25)
Ipeak=120A (Pause<10us) Ipeak=140A (Pause<10us)
 - CPU MLCC:** 16'10uF


CPU SMT, Ex. CORE-MAX	I _{max} (DRM=1000 uV/V)	CPU Gain Setting	Equivalent Gain
Maximum CPU Core Current	[A]	Set on Platform via CSC Lines	(mV)
Feature disabled		000	
10A core max @ 20 A	20	001	40.0
20A core max @ 40 A	40	010	30.0
30A core max @ 60 A	60	011	22.5
40A core max @ 80 A	80	100	18.0
50A core max @ 100 A	100	101	15.0
60A core max @ 120 A	120	110	12.9
70A core max @ 140 A	140	111	10.0

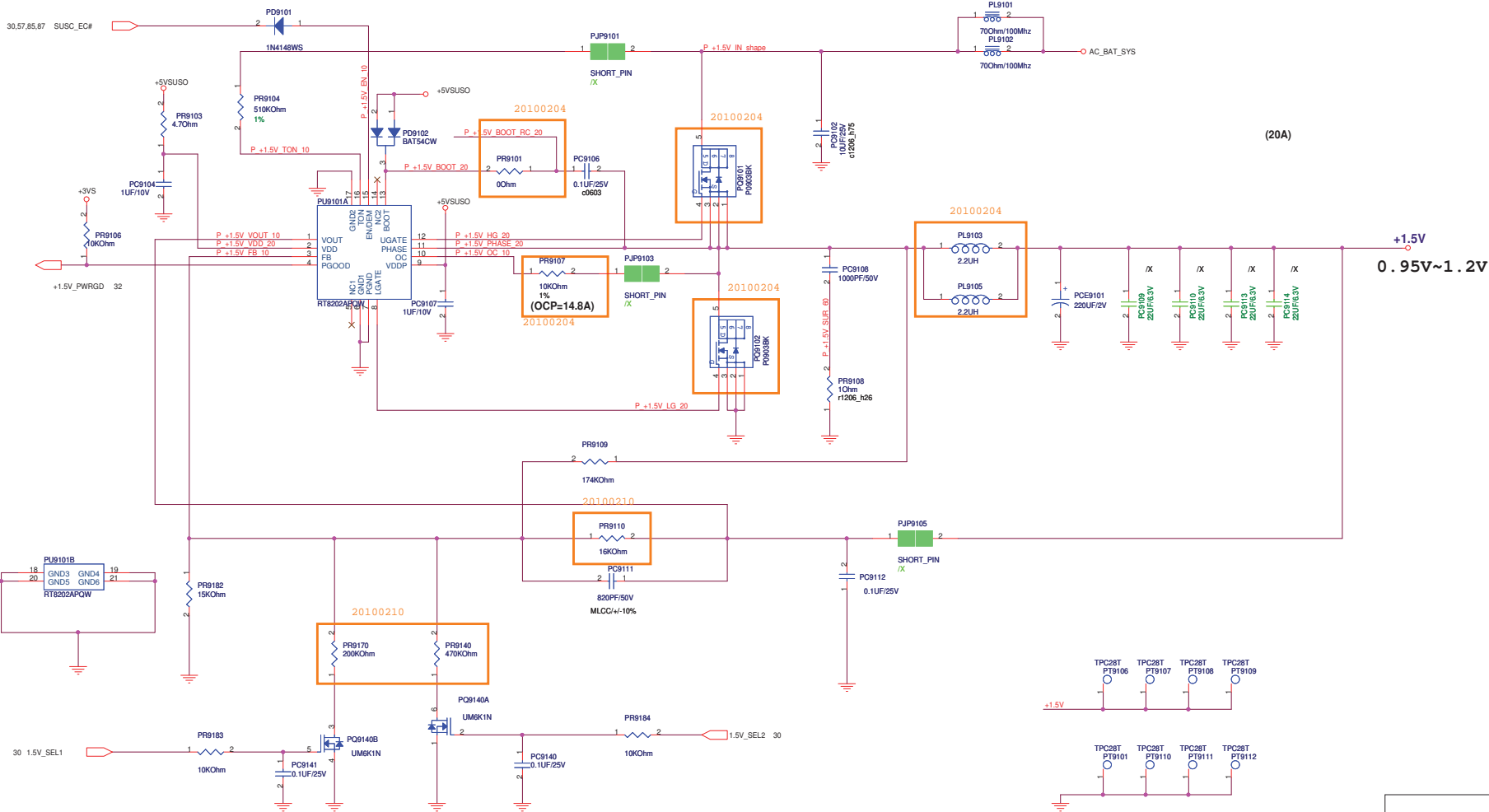
- VID[2:0] "Reserved" - default VID[2:0]='111' - option to change default should be provided on the motherboard.
- VID[5:3] will be used to provide IMON gain setting to CPU during CSC (see Section 3).
- VID[6] "Reserved" - default VID[6]='0' - option to change default should be provided on the motherboard.
- DPRSLPVR will be used to identify type of CPU core VR controller. DPRSLPVR='1' for IMVP-6.3-compliant controller.
- PSI# - "Reserved" - default PSI#='0' - option to change default should be provided on the motherboard.

VCORE_SEL1	VCORE_SEL2	+VCORE
0	0	VID - 23.9mV
0	1	VID - 17.4mV
1	0	VID - 12.9mV
1	1	VID



<Variant Name>

		Title : Power_Charger	
ASUSTek Computer INC.		Engineer: Limy_II	
Size	Project Name		Rev
A3	F83T		2.1G
Date:	Thursday, February 11, 2010		Sheet 90 of 1



0.75VS / 0.5A

1.5V_SEL1	1.5V_SEL2	+1.5V	
0	0	1.483V	DV3
0	1	1.506V	DV2
1	0	1.538V	DV1
1	1	1.561V	Normal

Controller

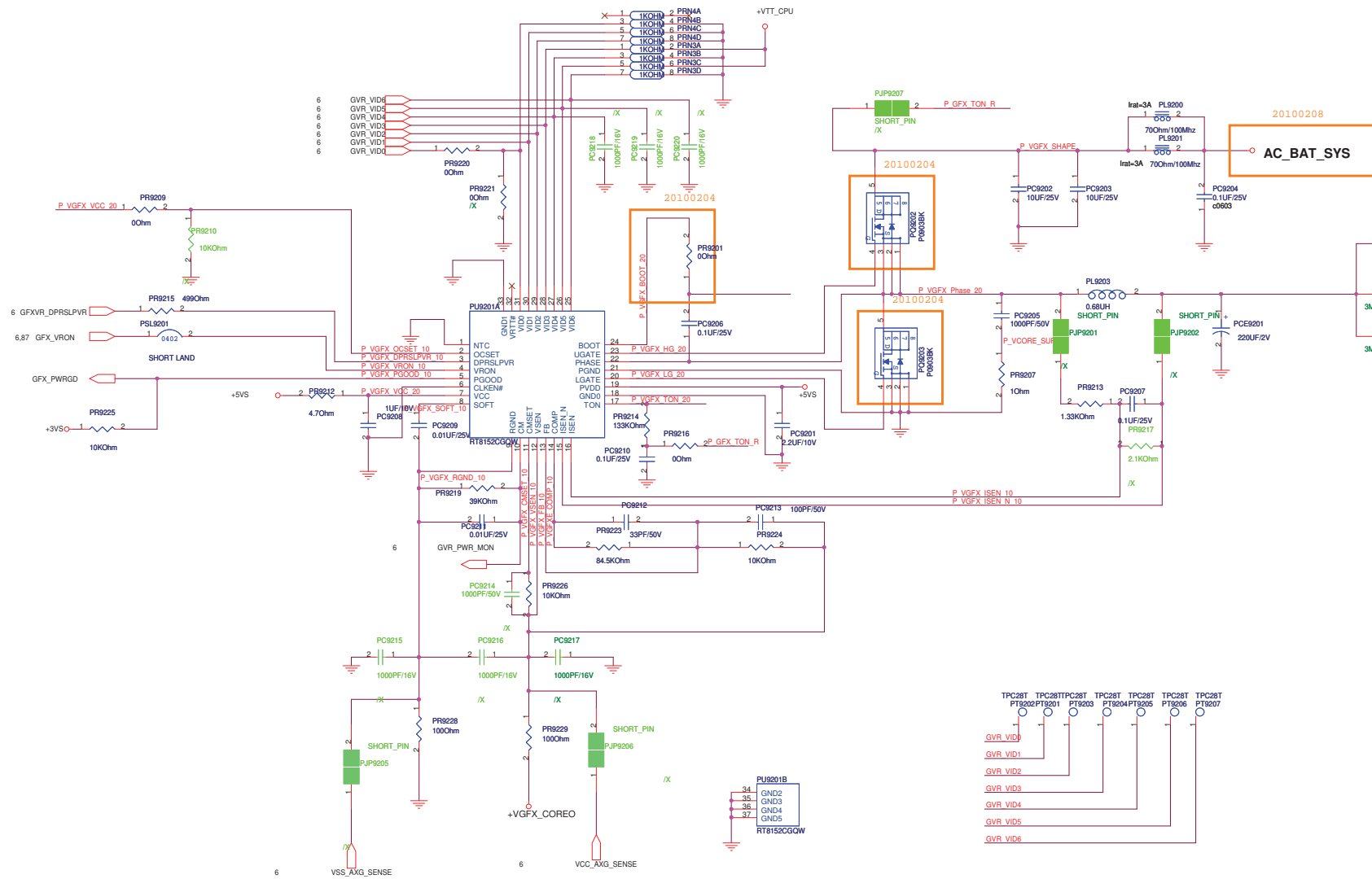
- 1. Voltage & Current:**
+1.2VSUS: 16A
- 2. Frequency:**
Ton=3.85p*Rt(on)/Vin-05=0.3us
Frequency=Vout/(Vin*Ton)
=500KHz
- 3. OCP:**
Set PR8107=21.5kohm
Iocp=Rocp*20/Rds(on)=26A
- 4. Soft start time:**
Soft-Star duration is 1.35ms
- 5. Inrush Current:**
C total =220uF
I inrush=0.163A

Power stage

- 1. I/P Current:**
 $I_{in} = V_o I_o / (0.75 * V_{in}) = 0.85A$
- 2. Ripple Current:**
Iripple=3.74A
- 3. ripple voltage:**
 $I_{peak} = (V_{in} - V_o) * D / (L * F_{sw}) = 2.07A$
DCR=3.3mohm
V=6.831mV
- 4. Inductor Spec:**
Isat=25A
Idc=15.5A
DCR=5.5mohm
- 5. MOSFET Spec:**
H-side and L-side MOSFET:
Rds(on)=16.5mOhm (Vgs=4.5V)
Icont=30A (T=25)
Ipeak=120A (Pause<10us)

<Variant Name>

ASUS		Title : +1.5V	
ASUSTek COMPUTER INC		Engineer:	
Size	Project Name		Rev
C	K80A		1.0
Date: Thursday, February 11, 2010		Sheet	91 of 91

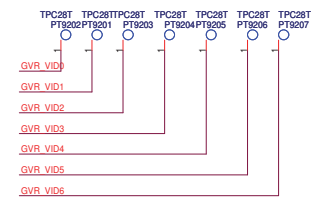


Controller

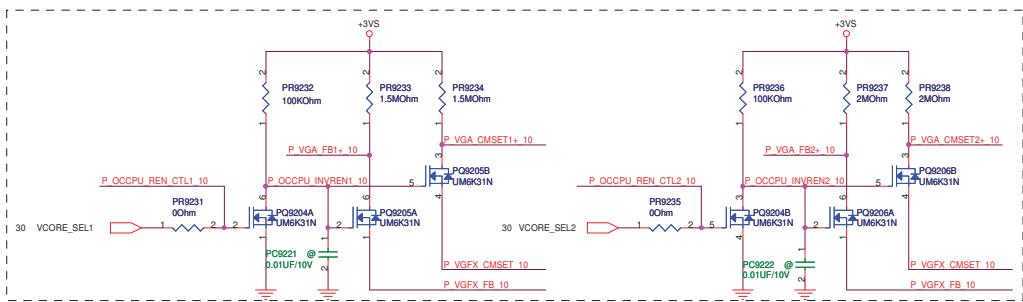
- Voltage & Current:**
+VGFX_CORE:1V/15A
- Frequency:**
 $Ton = Cton \cdot (Rton + 6.5K)$
 $Cton = 16.26PF$
 $fsw = 309KHZ$
- OC:**
 $Vocset = 40\% \cdot Ilim \cdot R_{sense}$
 $I_{max} = 30A$
- On time:**
 $Ton = Tsw \cdot (Vfb + 0.075) / Vin = 354ns$
- LoadLine:**
 $Rdroop = \Delta I \cdot R_{sense} \cdot R1/R2$
 $= 7mohm$

Power stage

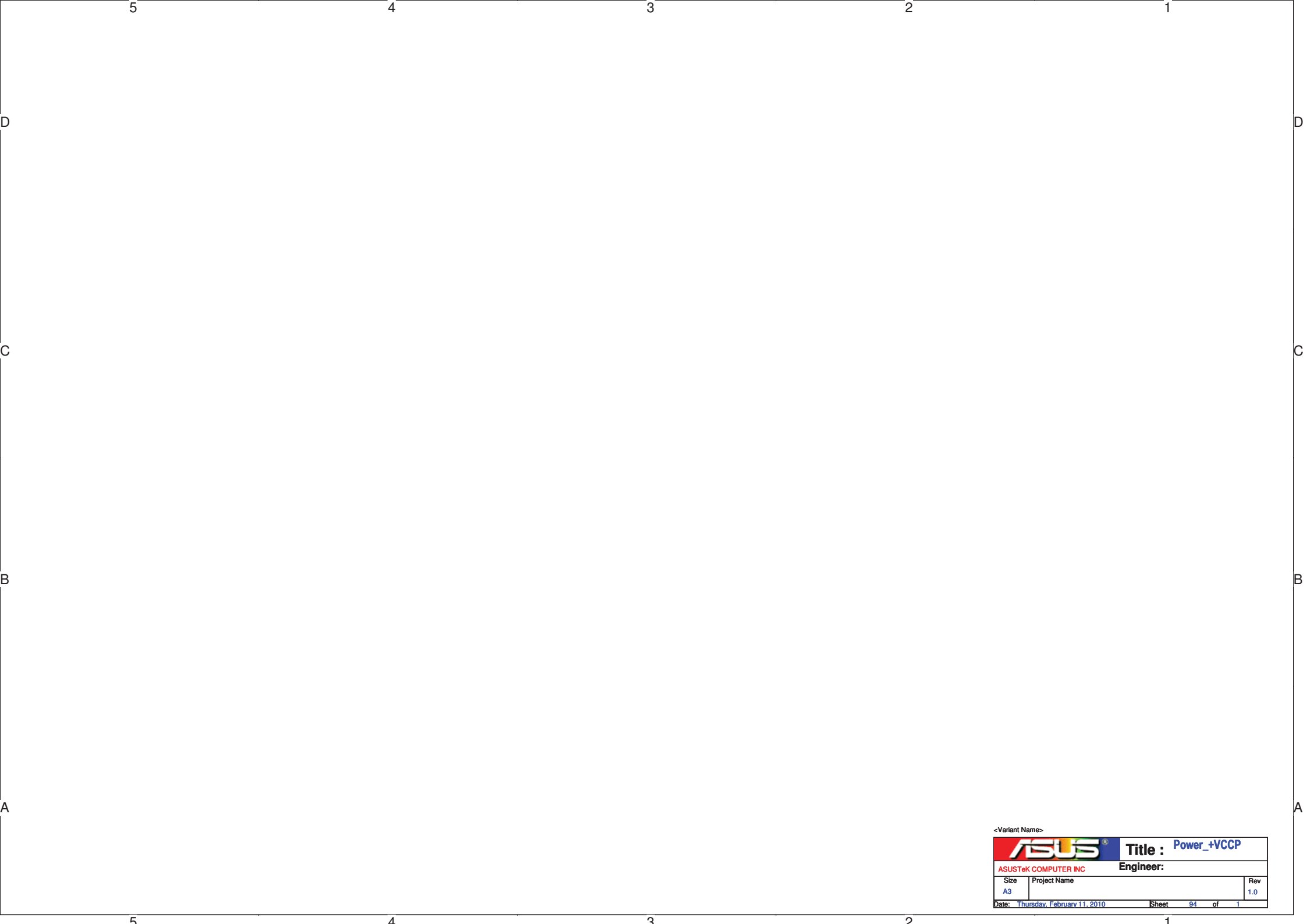
- I/P Current:**
 $I_{in} = Vo \cdot Io / (0.75 \cdot Vin) = 1.33A$
- Ripple Current:**
 $I_{ripple} = 3A$
- Ripple Voltage:**
 $V_{ripple} = I_{ripple} \cdot ESR = 13.5mV$
- Dynamic:**
 $I_{peak} = 10A$
 $ESR = 4.5mohm$
 $V = 40.5mV$
- Inductor Spec:**
 $I_{sat} = 25A$
 $I_{dc} = 15.5A$
 $R_{dcmax} = 5.5mOhm$
 $R_{dcmtyp} = 5mOhm$
- MOSFET Spec:**
H-side and L-side MOSFET: RJK0355
 $R_{ds(on)} = 11.8mOhm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25$)
 $I_{peak} = 120A$ (Pause < 10us)

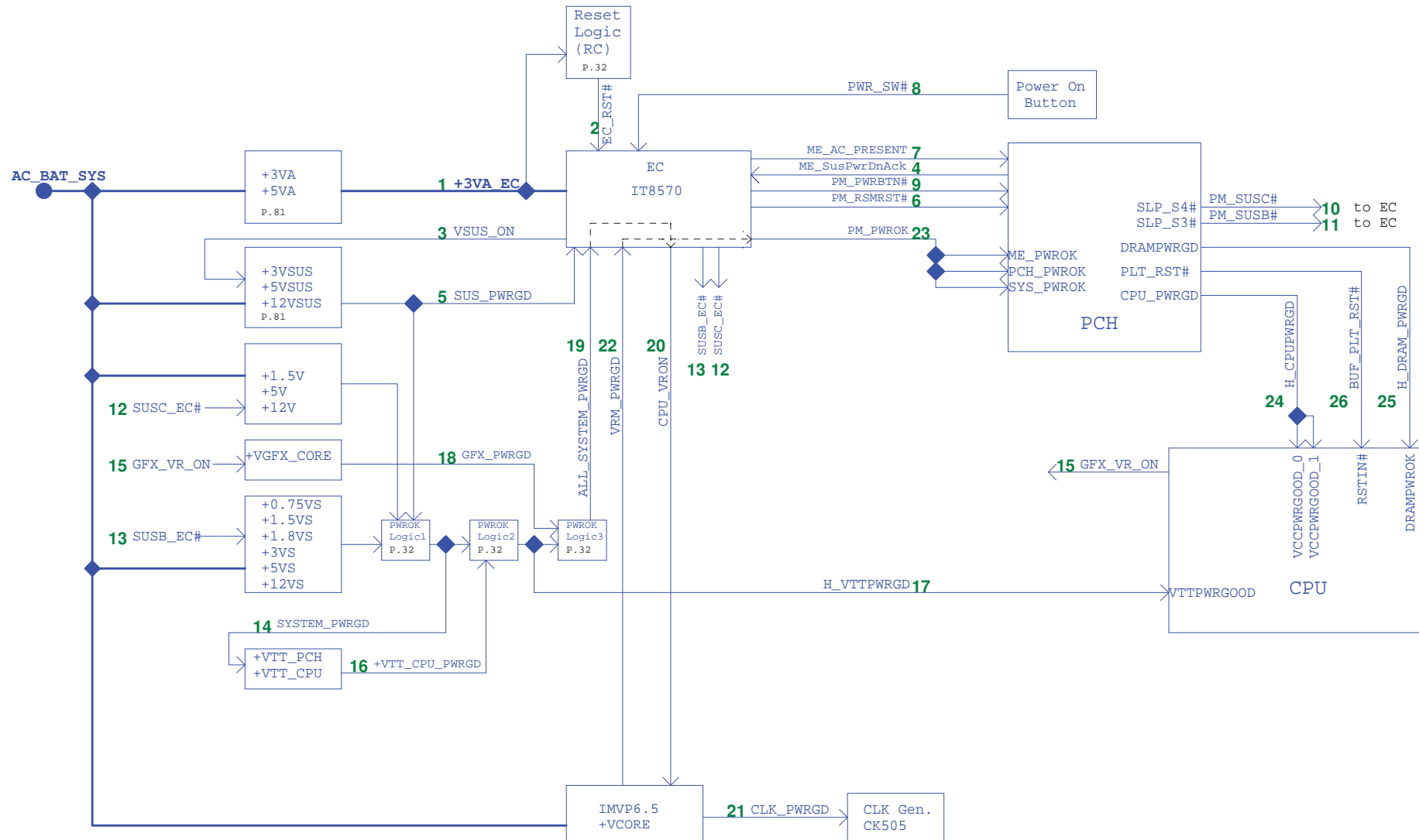


VCORE_SEL1	VCORE_SEL2	+VGFX_CORE
L	L	VID - 26.8mV
L	H	VID - 15.3mV
H	L	VID - 11.5mV
H	H	VID



<Variant Name>



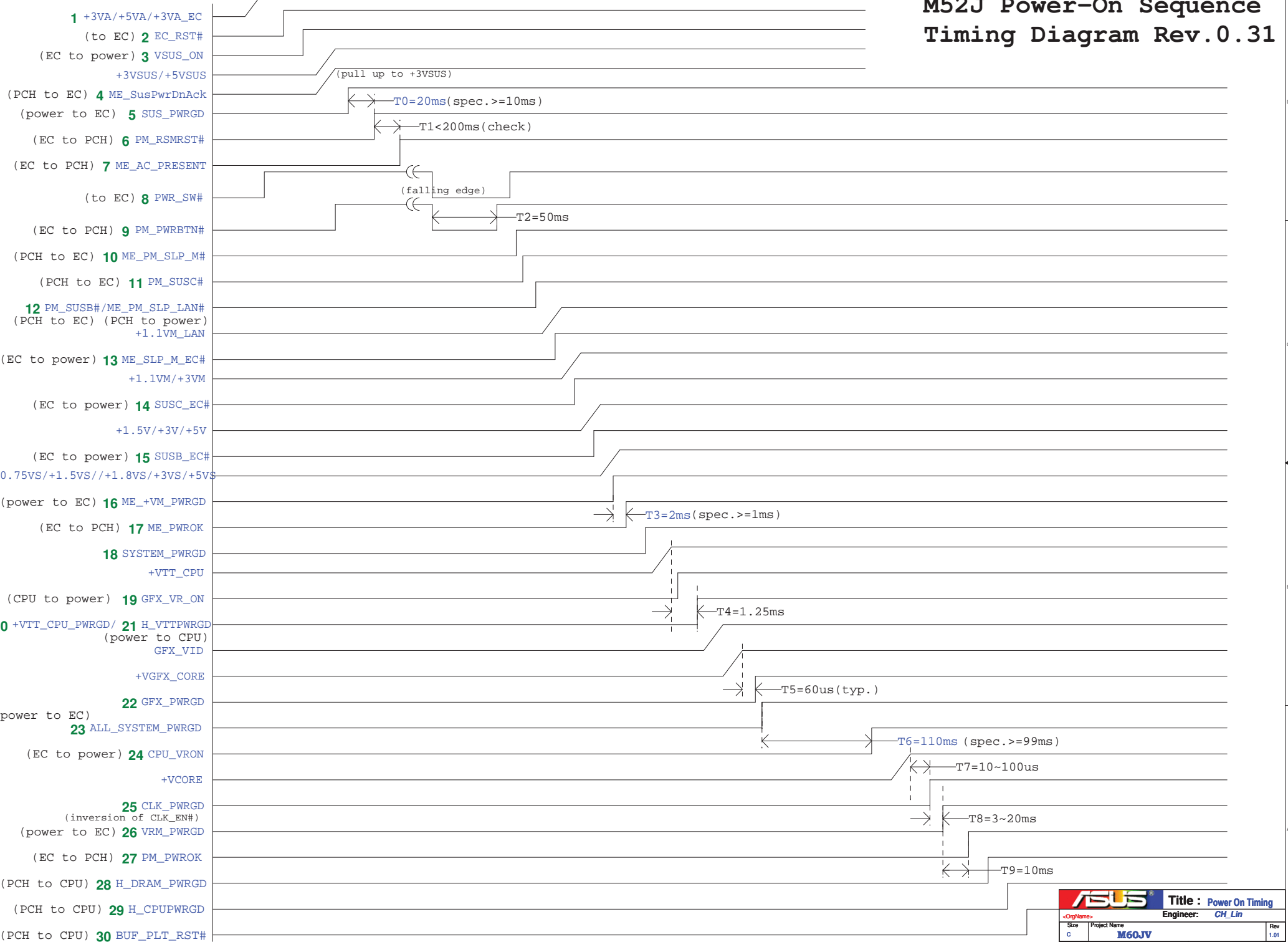


Power On Sequence

1 → 26

AC-IN Mode

M52J Power-On Sequence
Timing Diagram Rev.0.31



DC-IN Mode

M52J Power-On Sequence
Timing Diagram Rev.0.31

